



For more information
Please visit
the official website
of DELEC.

www.delec.cn
www.delec.com.cn

Dongguan Factory 『东莞工厂』

地址：中国广东省东莞市横沥镇田绕步村长田路45号

Add: 45th Changtian Rd., Tianraobu, Hengli, Dongguan, Guangdong China

TEL: +86 769 8101 1258

Email: mailbox@delec.com.cn

Foshan Factory 『佛山工厂』

地址：佛山市顺德区伦教熹涌工业区解放路南1号C座

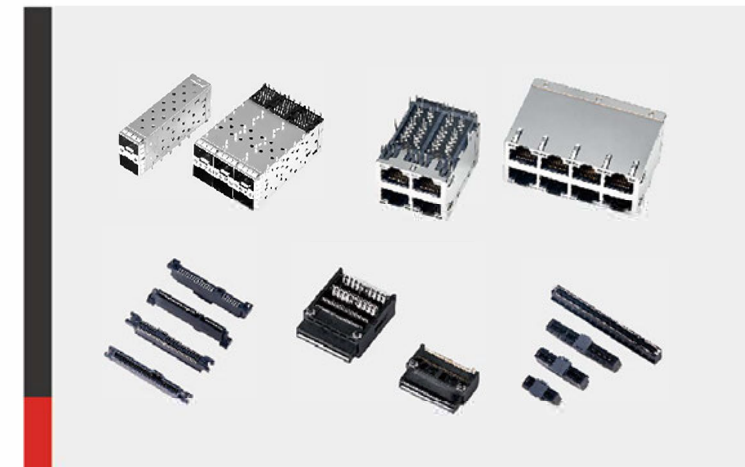
Add: BLK C, 1 Jie Fang Road, Xiyong Countryside, Lun Jiao, Shunde, Foshan, CN

TEL: +86 757 2733 6673

Email: info@delec.com.cn



DELEC[®]
Connectors



东莞市多亚电子有限公司

Duoya Electronics Company Limited



PDF
ONLINE CATALOG

in Producing Connectors And Cables



Brief introduction

Established in December 1997, DELEC is a rapidly expanding company in the telecommunications and computer interconnector market. We produce a wide array of telecommunications jacks and computer connectors.

Quality is the core value in our company. We believe quality is the driving force to our success and support from our partner. Being a certified ISO 9001:2004 company makes us vigilant and demanding on our products. With our ISO 14001 in 2001, we take precaution in protecting the environment. All of our product lines also meet UL and CUL safety standards.

We have developed innovative designs for a variety of integrated network interface modules that vary in application. Our latest series of interface modules include increase in density, reduction in modular components that deliver greater value to customers. Our design efforts on 10 baseT, 10/100 TX, Gigabit magnetic electronics components, and RJ-45 metal screen covers have been widely accepted and are the industry standard.

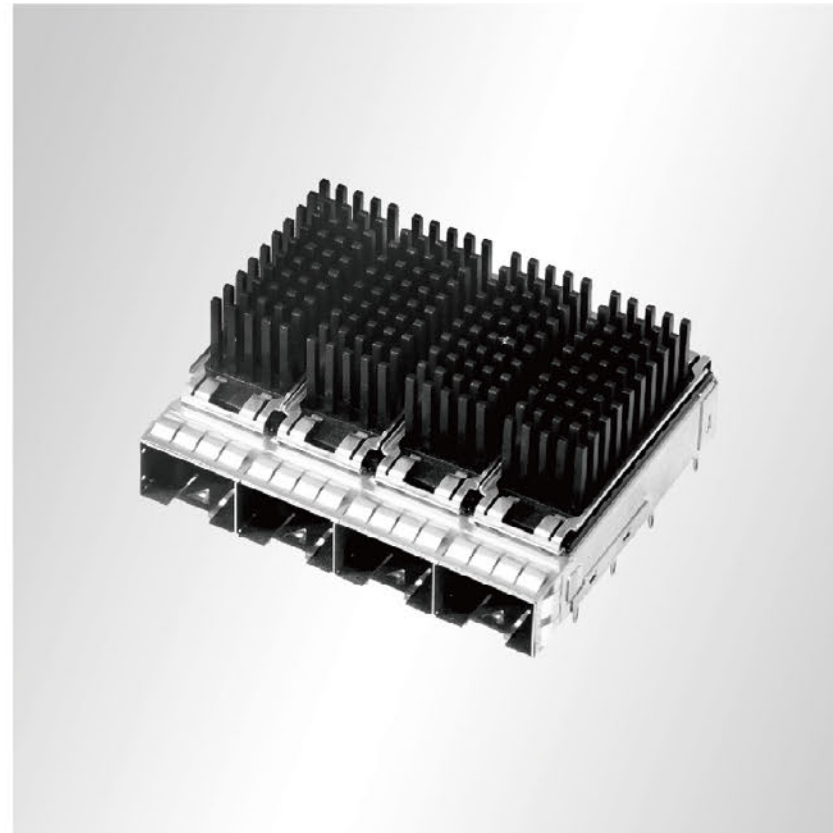
Our Goals

- 1) Continue to develop new and innovative designs for all product offerings;
- 2) Maintain a people-oriented team with high integrity that will help to expand our company;
- 3) Provide excellent quality customer service and maintain long term relationships with our customer;
- 4) Provide improved customer service with future ERP and CRM support.

Quality Certification



Single & Rows SFP, SFP+, SFP28, SFP56



Specification Highlights

The interconnect system is comprised of a cage assembly which is used with 20-position SFP connectors complying with MSA Agreement INF-8074i and SFF-8081 and SFF-8083 and SFF-8432 and SFF-8433.

Configurations(Rows x Ports per Row)

- 1x1 1x2 1x4 1x6
- 2x1 2x2 2x3 2x4 2x6 2x8 2x12

General Characteristics

1. RoHS Compliant
2. Industry Standard Footprint
3. Industry Standard EIA-364

Mechanical Characteristics

1. Compliant Press-Fit Pins or Solder Tails (Single Ports)
 2. Durability: 250 Mating Cycles min
- Electrical Characteristics
1. Hot Swappable
 2. Operating Voltage: 3.3V
 3. Operating Current: 0.5A
 4. Differential Impedance: 100Ω $\pm$ 10Ω
 5. DWV: 300 V AC
 6. Insulation Resistance: 1000MΩmin
 7. Contact Resistance: 70mΩmax

Materials

1. Cage/Base Material: Copper Alloy
Light Pipe: Optical Grade Polycarbonate
Heat Sink: Aluminum Alloy
Heat Sink Clip: Stainless Steel
Dust Cover: Thermoplastic
EMI Ground Tabs: Stainless Steel
2. Connector
Contact Base Material: Copper Alloy
Contact Plating: Gold on Mating Area, Gold or Matte Tin on Termination
Housings: Glass Reinforced, Lead-Free Solder
Reflow Process Compatible Thermoplastic, UL94V-0 Rated

Temperature Rating

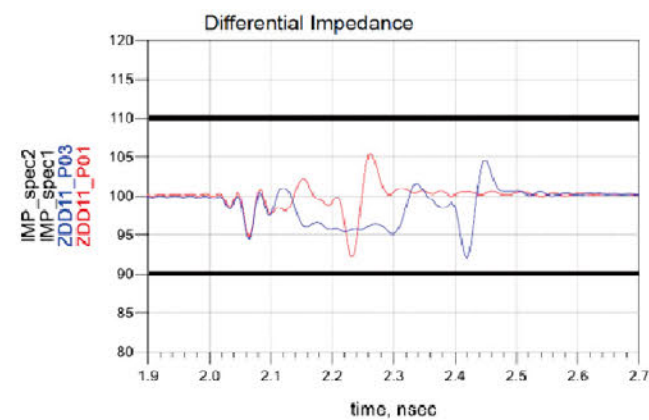
1. Operating Temperature: -40°C to +85°C
2. Storage Temperature: -55°C to +105°C

Options

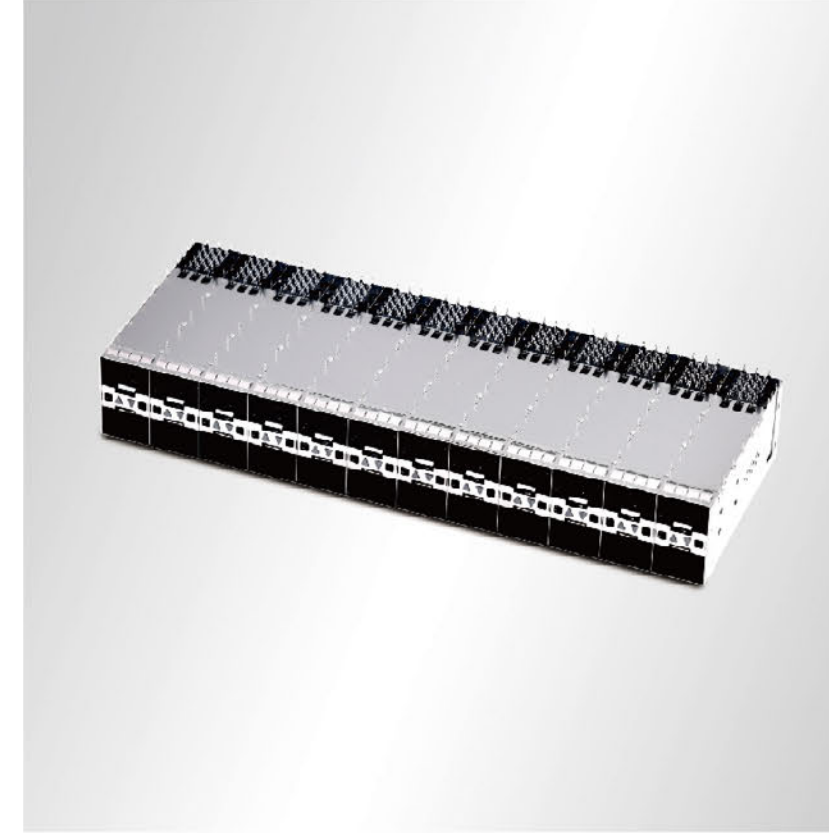
1. Dust Cover
2. Light Pipe (Inner Light Pipes or Outer Light Pipes)
3. Heat Sink
4. EMI Spring Fingers
Metal Spring Fingers
Conductive Elastomeric Gasket

Packaging

1. Tray Packaging: Cage and Connector Assembly
2. Bulk Packaging: Dust Cover



Stacked SFP, SFP+, SFP28, SFP56



Specification Highlights

The interconnect system is comprised of a cage assembly which is used with 20-position SFP connectors complying with MSA Agreement INF-8074i and SFF-8081 and SFF-8083 and SFF-8432 and SFF-8433.

Configurations(Rows x Ports per Row)

1. 1x1 1x2 1x4 1x6
2. 2x1 2x2 2x3 2x4 2x6 2x8 2x12

General Characteristics

1. RoHS Compliant
2. Industry Standard Footprint
3. Industry Standard EIA-364

Mechanical Characteristics

1. Compliant Press-Fit Pins or Solder Tails (Single Ports)
2. Durability: 250 Mating Cycles min

Electrical Characteristics

1. Hot Swappable
2. Operating Voltage: 3.3V
3. Operating Current: 0.5A
4. Differential Impedance: 100Ω $\pm$ 10Ω
5. DWV: 300 V AC
6. Insulation Resistance: 1000MΩmin
7. Contact Resistance: 70mΩmax

Materials

1. Cage/Base Material: Copper Alloy
Light Pipe: Optical Grade Polycarbonate
Heat Sink: Aluminum Alloy
Heat Sink Clip: Stainless Steel
Dust Cover: Thermoplastic
EMI Ground Tabs: Stainless Steel
2. Connector
Contact Base Material: Copper Alloy
Contact Plating: Gold on Mating Area, Gold or Matte Tin on Termination
Housings: Glass Reinforced, Lead-Free Solder
Reflow Process Compatible Thermoplastic, UL94V-0 Rated

Temperature Rating

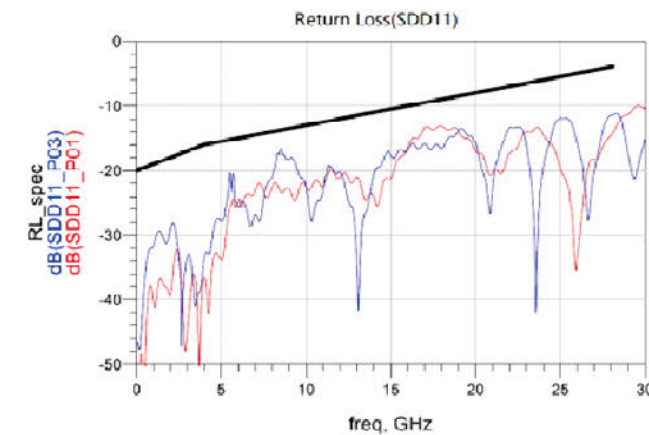
1. Operating Temperature: -40°C to +85°C
2. Storage Temperature: -55°C to +105°C

Options

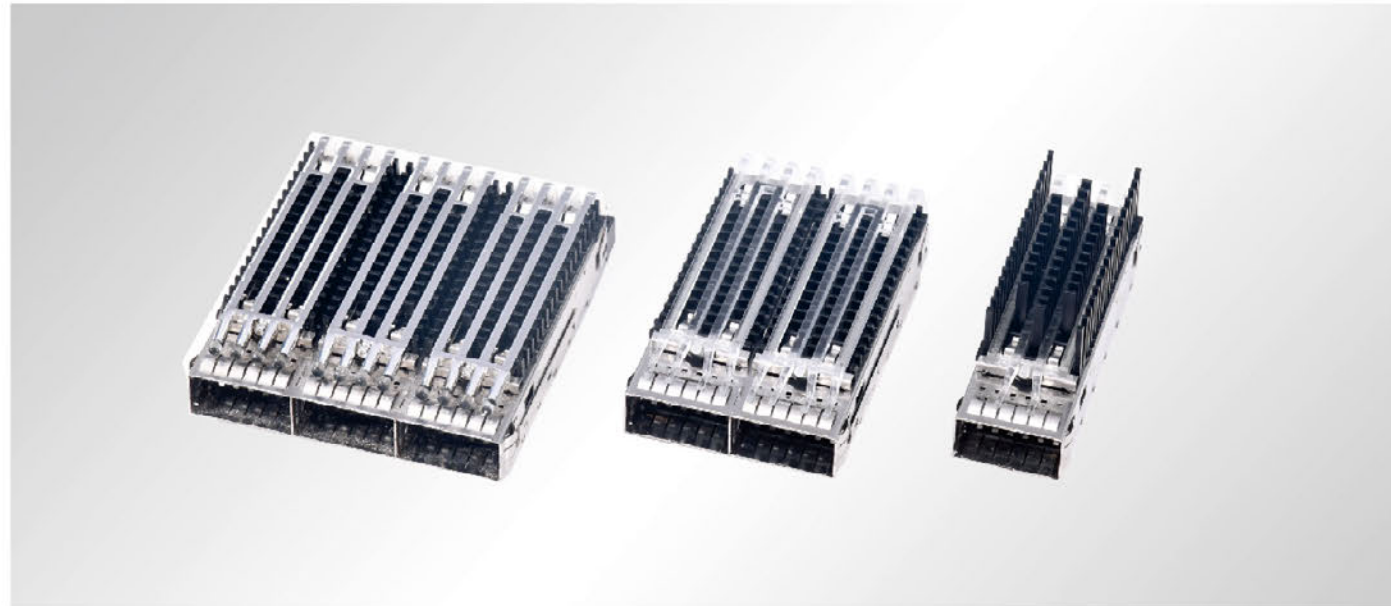
1. Dust Cover
2. Light Pipe (Inner Light Pipes or Outer Light Pipes)
3. Heat Sink
4. EMI Spring Fingers
Metal Spring Fingers
Conductive Elastomeric Gasket

Packaging

1. Tray Packaging: Cage and Connector Assembly
2. Bulk Packaging: Dust Cover



Single & Rows QSFP+ / QSFP28 / QSFP56 1×N Cage / Connector



Specification Highlights

The interconnect system is comprised of a cage assembly which is used with 38-position QSFP connectors complying with MSA Agreement SFF-8682 and SFF-8672 and SFF-8683 and SFF-8662 and SFF-8663.

Configurations(Rows x Ports per Row)

1. 1x1 1x2 1x3 1x4 General Characteristics
1. RoHS Compliant
2. Industry Standard Footprint
3. Industry Standard EIA-364

Mechanical Characteristics

1. Compliant Press-Fit Pins or Solder Tails (Single Ports)
2. Durability: 250 Mating Cycles min

Electrical Characteristics

1. Hot Swappable
2. Operating Voltage: 30VDC per contact
3. Operating Current: 0.5A
4. Differential Impedance: 100Ω±10Ω
5. DWV: 300 V AC
6. Insulation Resistance: 1000MΩmin
7. Contact Resistance: 70mΩmax

Materials

1. Cage: Base Material: Copper Alloy
Light Pipe: Optical Grade Polycarbonate
Heat Sink: Aluminum Alloy
Heat Sink Clip: Stainless Steel
Dust Cover: Thermoplastic
EMI Ground Tabs: Stainless Steel
2. Connector
Contact Base Material: Copper Alloy
Contact Plating: Gold on Mating Area, Gold or Matte Tin on Termination
Housings: Glass Reinforced, Lead-Free Solder Reflow
Process Compatible Thermoplastic, UL94V-0 Rated

Temperature Rating

1. Operating Temperature: -40°C to +85°C
2. Storage Temperature: -55°C to +105°C

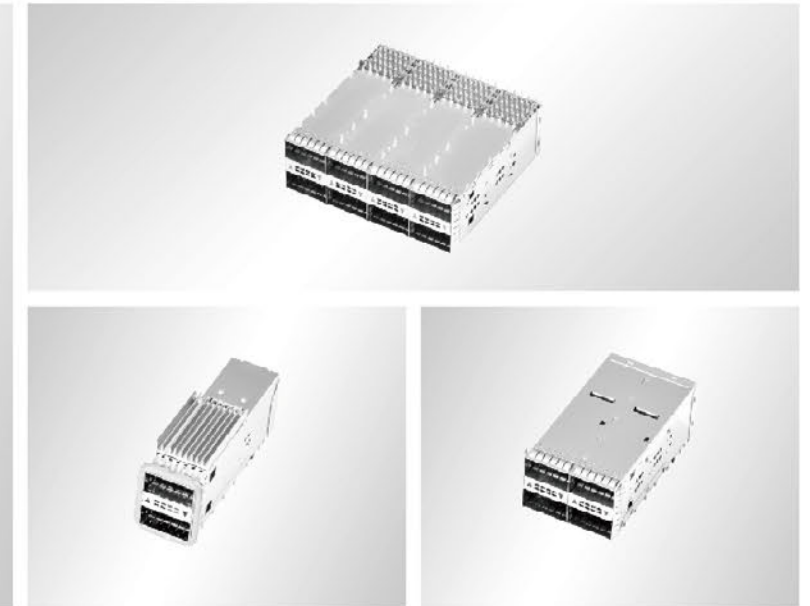
Options

1. Dust Cover
2. Light Pipe (Inner Light Pipes or Outer Light Pipes)
3. Heat Sink
4. EMI Spring Fingers
Metal Spring Fingers
Conductive Elastomeric Gasket

Packaging

1. Tray Packaging: Cage and Connector Assembly
2. Bulk Packaging: Dust Cover

Single / Stacked QSFP+ / QSFP28 / QSFP56 2×N Connector



Specification Highlights

The interconnect system is comprised of a cage assembly which is used with 38-position QSFP connectors complying with MSA Agreement SFF-8682 and SFF-8672 and SFF-8683 and SFF-8662 and SFF-8663.

Configurations(Rows x Ports per Row)

1. 2x1 2x2 2x3 2x4
- General Characteristics
1. RoHS Compliant
 2. Industry Standard Footprint
 3. Industry Standard EIA-364
- Mechanical Characteristics
1. Compliant Press-Fit Pins or Solder Tails (Single Ports)
 2. Durability: 250 Mating Cycles min
- Electrical Characteristics
1. Hot Swappable
 2. Operating Voltage: 30VDC per contact
 3. Operating Current: 0.5A
 4. Differential Impedance: 100Ω±10Ω
 5. DWV: 300 V AC
 6. Insulation Resistance: 1000MΩmin
 7. Contact Resistance: 70mΩmax

Materials

1. Cage: Base Material: Copper Alloy
Light Pipe: Optical Grade Polycarbonate
Heat Sink: Aluminum Alloy
Heat Sink Clip: Stainless Steel
Dust Cover: Thermoplastic
EMI Ground Tabs: Stainless Steel
2. Connector
Contact Base Material: Copper Alloy
Contact Plating: Gold on Mating Area, Gold or Matte Tin on Termination
Housings: Glass Reinforced, Lead-Free Solder Reflow
Process Compatible Thermoplastic, UL94V-0 Rated

Temperature Rating

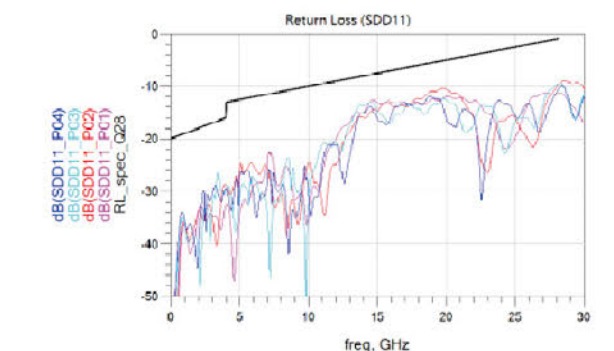
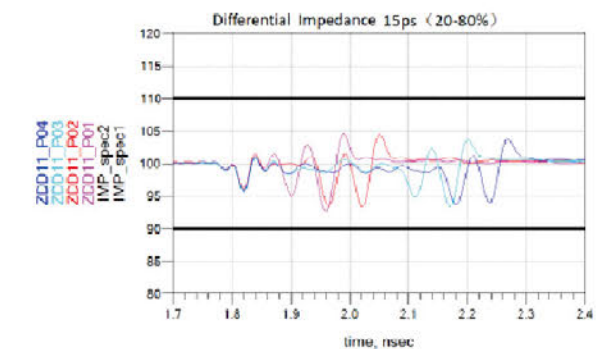
1. Operating Temperature: -40°C to +85°C
2. Storage Temperature: -55°C to +105°C

Options

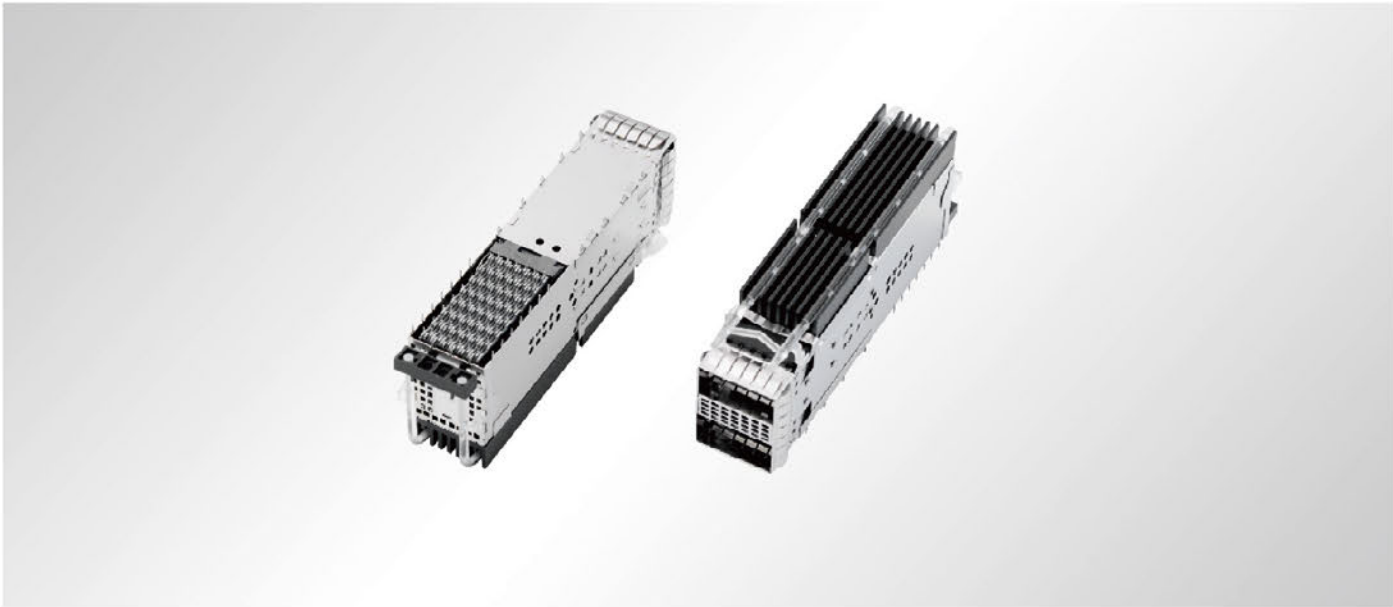
1. Dust Cover
2. Light Pipe (Inner Light Pipes or Outer Light Pipes)
3. Heat Sink
4. EMI Spring Fingers
Metal Spring Fingers
Conductive Elastomeric Gasket

Packaging

1. Tray Packaging: Cage and Connector Assembly
2. Bulk Packaging: Dust Cover



Single & Stacked SFP-DD&QSFP-DD



Specification Highlights
complying with SFP-DD MSA Agreement and INF-8628
Configurations(Rows x Ports per Row)
1. 1x1 2. 2x1 General Characteristics
1.Rohs Compliant

2.Industry Standard Footprint
3.Industry Standard EIA-364
Mechanical Characteristics
1.Compliant Press-Fit Pins or Solder Tails (Single Ports)
2.Durability:250 Mating Cycles min

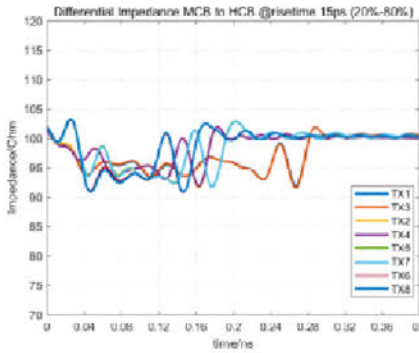
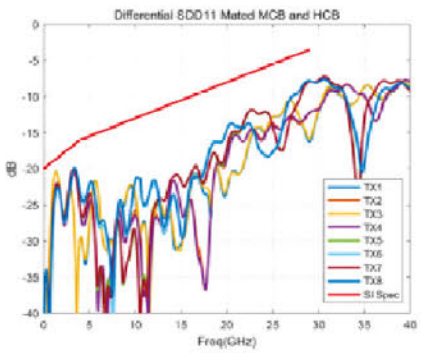
Electrical Characteristics
1. Hot Swappable
2.Operating Voltage:30VDC per contact
3.Operating Current:0.5A
4.Differential Impedance:100Ω +/-10Ω
5.DWV:300 V AC
6. Insulation Resistance:1000MΩmin
7.Contact Resistance:70mΩmax

Materials
1.Cage:Base Material: Copper Alloy
Light Pipe: Optical Grade Polycarbonate
Heat Sink: Aluminum Alloy
Heat Sink Clip: Stainless Steel
Dust Cover: Thermoplastic
EMI Ground Tabs: Stainless Steel

2.Connector
Contact Base Material: Copper Alloy
Contact Plating: Gold on Mating Area, Gold or Matte Tin on Termination
Housings: Glass Reinforced, Lead Free Solder Reflow Process
Compatible Thermoplastic, UL94V-0 Rated
Temperature Rating
1.Operating Temperature:-40°C to +85°C
2.Storage Temperature:-55°C to +105°C

Options
1.Dust Cover
2.Light Pipe(inner Light Pipes or Outer Light Pipes)
3.Heat Sink
4.EMI Spring Fingers
Metal Spring Fingers
Conductive Elastomeric Gasket

Packaging
1. Tray Packaging:Cage and Connector Assembly
2. Bulk Packaging:Dust Cover



Single & Rows CFP2 Cage/Connector



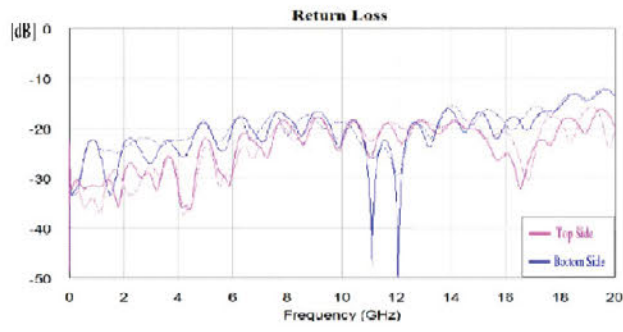
MATERIAL
1.Housing: Black color, Glass reinforced, Lead Free Solder Reflow Process Compatible
Thermo Plastic Contacts Base 2.Material: Phosphor Bronze
3.Plating Solder Tails: Matte tin
4.Plating Mating Area: Gold
5.Resonance Dampening Feature: Conductive Polymer

MECHANICAL PERFORMANCE
1.Durability: 200 mating cycles
Mating Force: 80 N max.
2.Contact Normal Force: 30 grams
3.PCB Thickness (Cage): 3.00 mm (0.118 in.) Unmating Force (Cage): 50 N

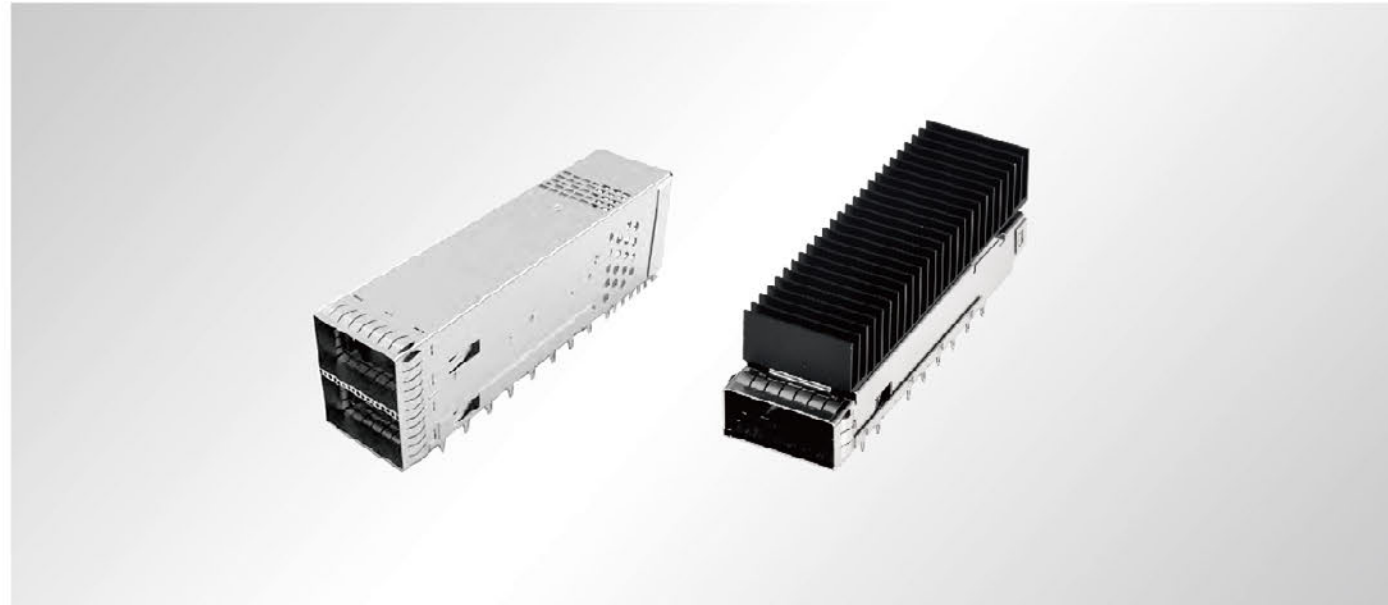
ELECTRICAL PERFORMANCE
1.Operating Voltage: 3.3 V DC per contact
(Class 4 or lower) / 1.25A maximum (Class 5 and 6)
2.Operating Current (per signal pin): 0.5A maximum

ENVIRONMENTAL
1.Operating and (Storage) Temperature: -40°C to +85°C
2.RoHS

TOOLING INFORMATION
Configurations: 1X1



Single & Stacked OSFP Connector



MATERIAL

1. Housing: Black color, Glass reinforced, Lead Free Solder Reflow Process Compatible Thermo Plastic
2. Contacts Base Material: Phosphor Bronze Plating Solder Tails: Matte tin over Nickel
3. Plating Mating Area: Gold
4. Resonance Dampening Feature: Carbon fibre reinforced

MECHANICAL PERFORMANCE

1. Durability: 250 mating cycles
2. Mating Force: 40 N max.
3. Unmating Force: 40 N max.
4. Contact Normal Force: 40 grams min.

ELECTRICAL PERFORMANCE

1. Operating Voltage: 30 VDC per contact
2. Operating Current:
3. 0.5 A per signal contact
4. 1.5 A per low speed power contact
5. Differential Impedance: 100Ω +/- 10Ω

ENVIRONMENTAL

1. Operating and (Storage) Temperature: -20° to +85° C
2. RoHS & Halogen-Free

TOOLING INFORMATION

1. Configurations:

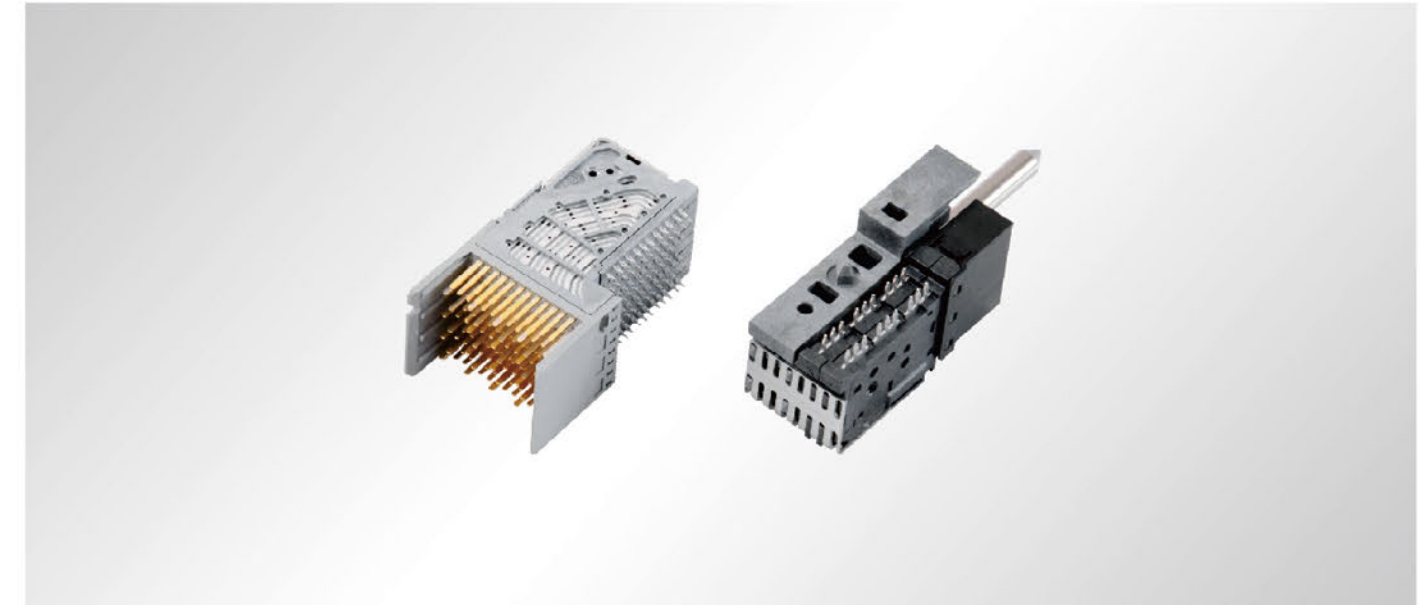
- (1) 1x1
- (2) 2x1

PACKAGING

Tape and Reel or Tray



High Speed Backplane Connector



High Speed Backplane Connectors

Material

Signal Contact: Copper Alloy
Ground Contact: Copper Alloy
Housing: Liquid Crystal Polymer UL 94V-0
Plating: 30" Ni
Compliant Pin Plating: RoHS

Feature

Temperature Range: -65°C to 90°C
Current Rating: 0.5A/contact @-30°C
Durability: 200 cycles
Voltage: 560 VAC
Operating Voltage: 250 VAC

Signal

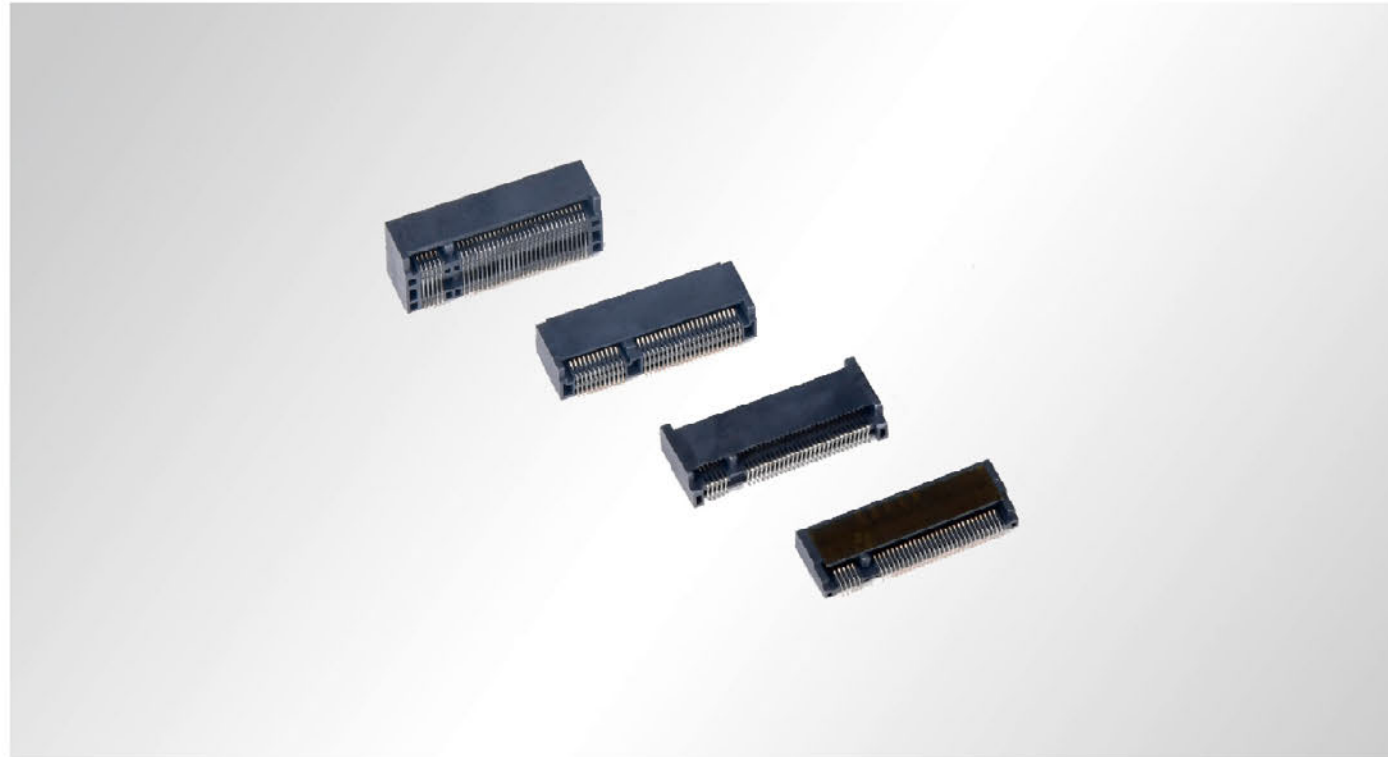
Impedance: Differential @100 ohms ±10%
Crosstalk: Multi-pair Differential crosstalk 2.1% @50ps
Insertion Loss: -2dB @10GHz

Specification

10+ Gbps performance
100 ohm impedance
Max 66 differential pairs/inch
50 Gbps @1B HDR
56.1 Gbps @128GFC



Card Edge Product Family: M.2



MECHANICAL PERFORMANCE

- 1.Insertion force (module to connector): 25N max
- 2.Terminal retention force: 100gf min.
- 3.Durability: 25cycles

ELECTRICAL PERFORMANCE

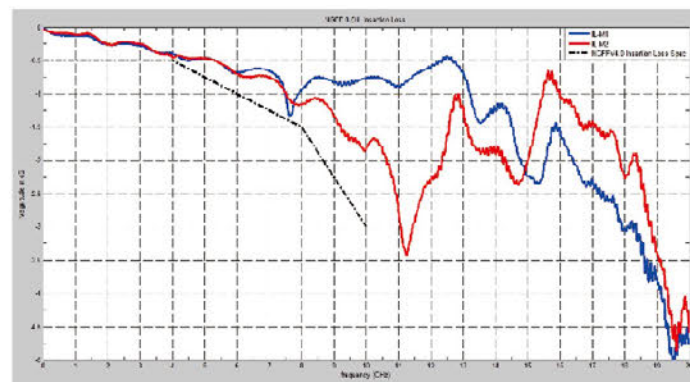
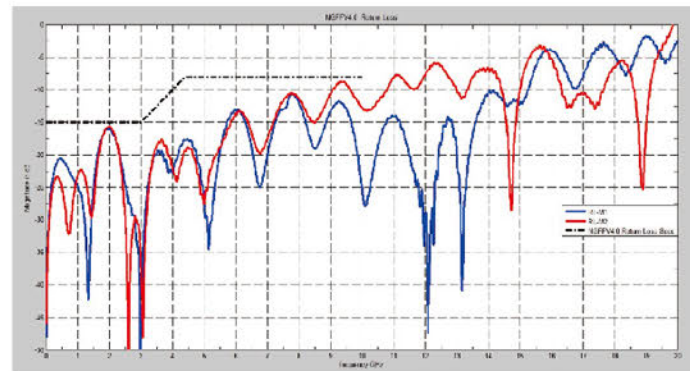
- 1.Low level contact resistance: 55mΩ initial, Δ20mΩ
- 2.Insulation resistance: 100MΩ min.
- 3.Dielectric withstanding voltage: 300VAC.
- 4.Current rating: 0.5A/pin De-rate

ENVIRONMENTAL

- 1.Flammability: UL 94 V-0
- 2.Low halogen: 1000ppm max. Cl, 1000ppm max Br.
- 3.Compliant with RoHS directive 2011/65/EU
- 4.Operating Temperature: -40°C to + 80°C

SPECIFICATION

- 1.PCI Express M.2 SPEC.
- 2.DELEC PRODUCT SPEC: DE-PS-0024



Internal High speed IO Series: MCIO/4X/8X16X



MECHANICAL PERFORMANCE

- 1.Insertion force: 1.15N/Pair max.
- 2.Unmating force: 0.10N/Pair min.
- 3.Terminal retention force: 200gf min.

ELECTRICAL PERFORMANCE

- 1.Low level contact resistance: 20mΩ initial, Δ10mΩ
- 2.Insulation resistance: 1000MΩ min.
- 3.Dielectric withstanding voltage: 300VAC.
- 4.Current rating: 1.0A/pin De-rate

ENVIRONMENTAL

- 1.Flammability: UL 94 V-0
- 2.Low halogen: 1000ppm max. Cl, 1000ppm max Br.
- 3.Compliant with RoHS directive 2011/65/EU
- 4.Operating Temperature: -55°C to + 85°C

SPECIFICATION

- 1.JEDEC SPEC:
Industry specification SFF-TA-1016
- 2.DELEC PRODUCT SPEC:
DE-PS-0088



Card Edge Product Family: PCI Express5.0/X1/X4/X8/X16



MECHANICAL PERFORMANCE

- 1.Insertion force (module to connector): 1.15N/Pair max.
- 2.Unmating force: 0.15N/Pair min.
- 3.Terminal retention force: 200gf min.
- 4.Durability: 50cycles.

ELECTRICAL PERFORMANCE

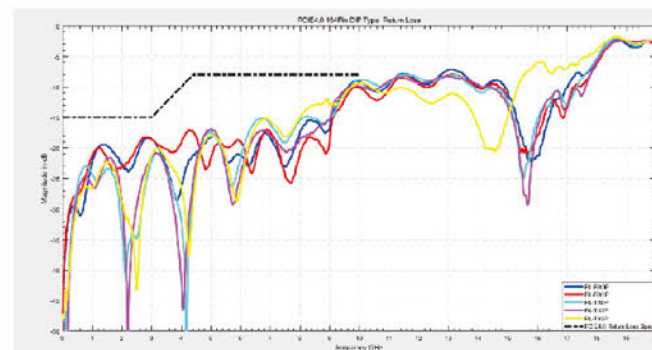
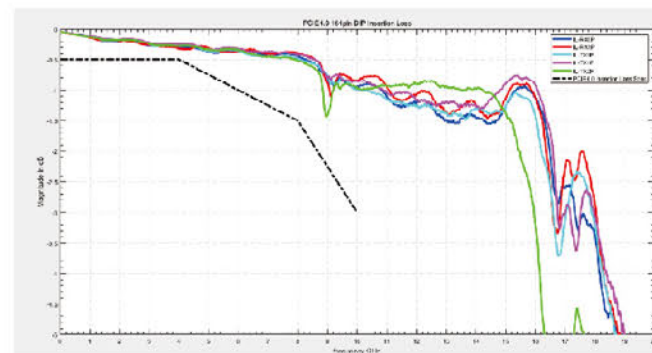
- 1.Low level contact resistance: 30mΩ initial, Δ10mΩ
- 2.Insulation resistance: 1000MΩ min.
- 3.Dielectric withstanding voltage: 500VAC.
- 4.Current rating: 1.0A/pin De-rate

ENVIRONMENTAL

- 1.Flammability: UL 94 V-0
- 2.Low halogen: 1000ppm max. Cl, 1000ppm max Br.
- 3.Compliant with RoHS directive 2011/65/EU
- 4.Operating Temperature: -40°C to + 85°C

SPECIFICATION

- 1.PCI Express card electromechanical specification
- 2.DELEC product spec:
DE-PS-0088



Card Edge Product Family: SLIVER 224CKTS STRADDLE MOUNT



MECHANICAL PERFORMANCE

- 1.Insertion force (AIC to connector): 1.1N/pair max
- 2.Unmating force: 0.1N/pair min.
- 3.Durability: 25cycles.

ELECTRICAL PERFORMANCE

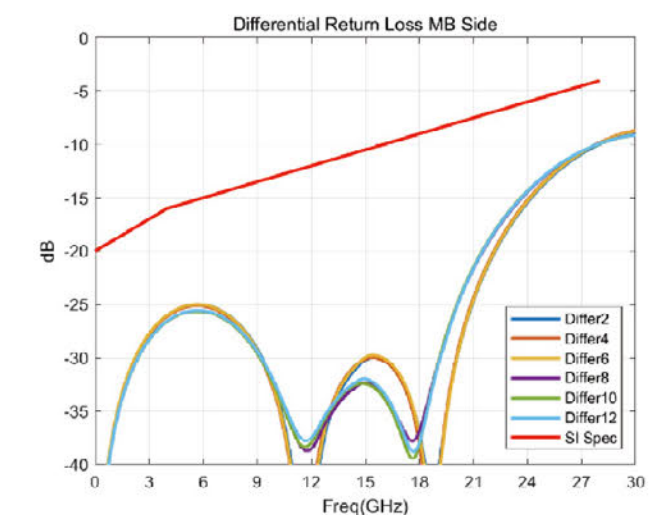
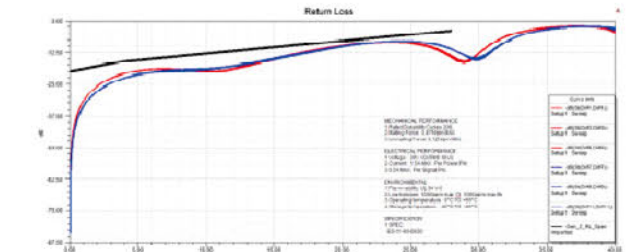
- 1.Low level contact resistance: 30mΩ initial, Δ15mΩ
- 2.Insulation resistance: 100MΩ min.
- 3.Dielectric withstanding voltage: 300VAC.
- 4.Current rating: 1.1A/pin De-rate

ENVIRONMENTAL

- 1.Flammability: UL 94 V-0
- 2.Low halogen: 1000ppm max. Cl, 1000ppm max Br.
- 3.Compliant with RoHS directive 2011/65/EU
- 4.Operating Temperature: -55°C to + 85°C
- 5.Thermal shock: 5 cycles between -55°C to +85°C
- 6.Temperature life: 105°C for 168 hours.

SPECIFICATION

- 1.SPEC:
SFF-TA-1002



U.3 Connector(SAS 3.0 7+15PIN/SAS 3.0/SAS 4.0/SAS 5.0)



MECHANICAL PERFORMANCE

1. Rated Durability Cycles 200.
2. Mating Force: 0.87N/pin MAX.
3. Unmating Force: 0.12N/pin MIN.

ELECTRICAL PERFORMANCE

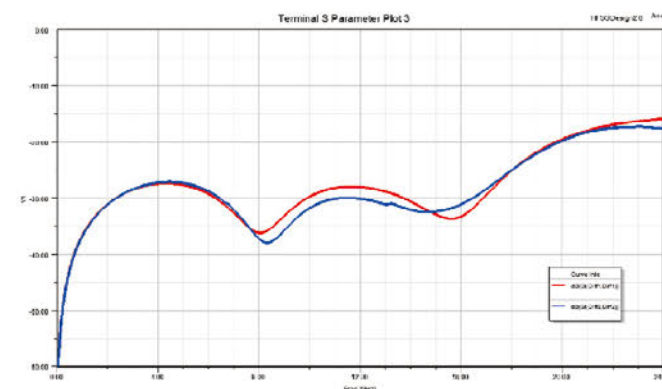
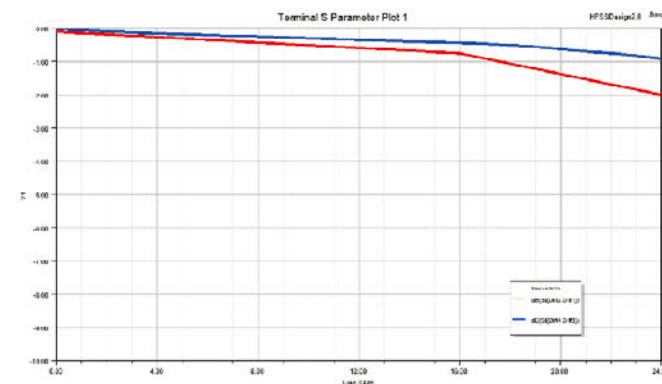
1. Voltage : 30V AC(RMS MAX)
2. Current : 1.5A MAX Per Power Pin
3. 0.5A MAX Per Signal Pin.

ENVIRONMENTAL

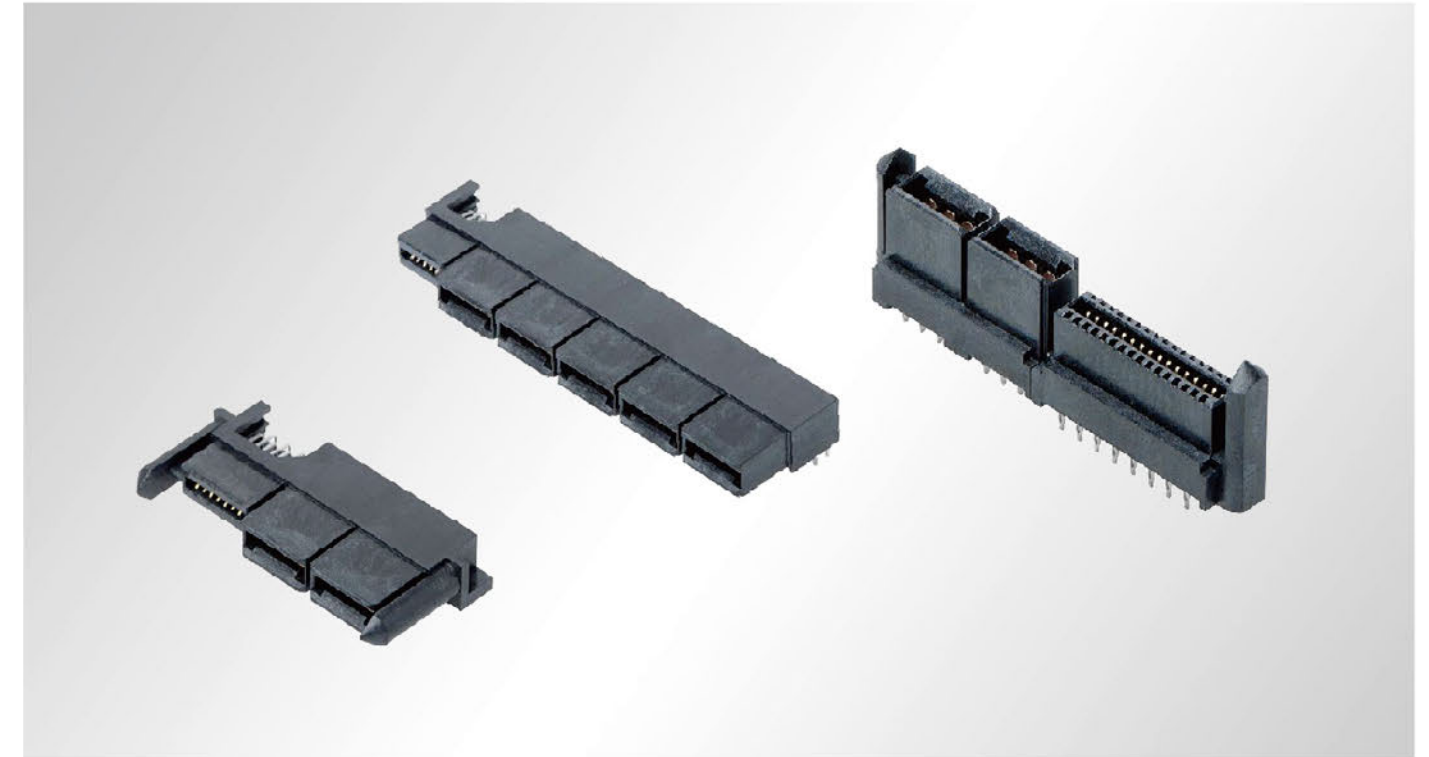
1. Flammability: UL 94 V-0
2. Low halogen: 1000ppm max. Cl, 1000ppm max Br.
3. Operating temperature : 0°C TO +55°C
4. Storage temperature : -40°C TO +85°C

SPECIFICATION

1. SPEC:
ES-11-00-0030



EXTreme LPHPower Connectors/Hybrid Right-Angle Receptacles



MECHANICAL PERFORMANCE

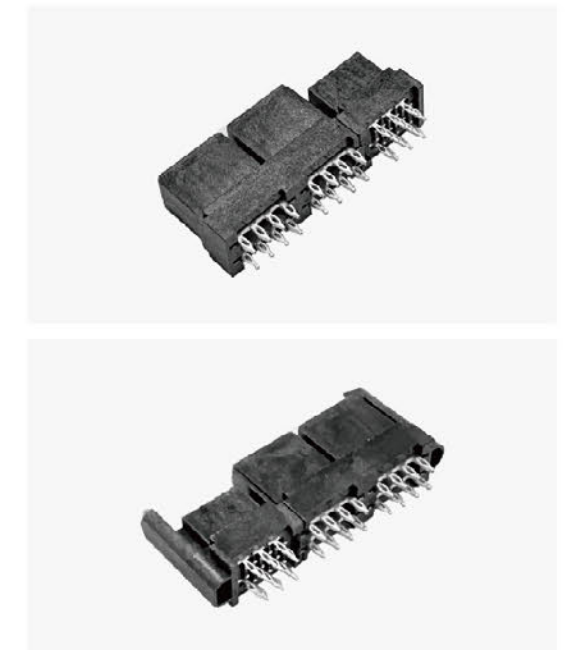
- Mating Force (max. per circuit):
Power Contacts-6.87N (1.54 lb.)
Signal Contacts- 1.08N (0.24 lb.)
Un-mating Force (min per circuit):
Power Contacts -1.47N (0.33 lb.)
Signal Contacts - 0.15N (0.03 lb.)
Durability: 250 cycles (receptacle and plug)

ELECTRICAL PERFORMANCE

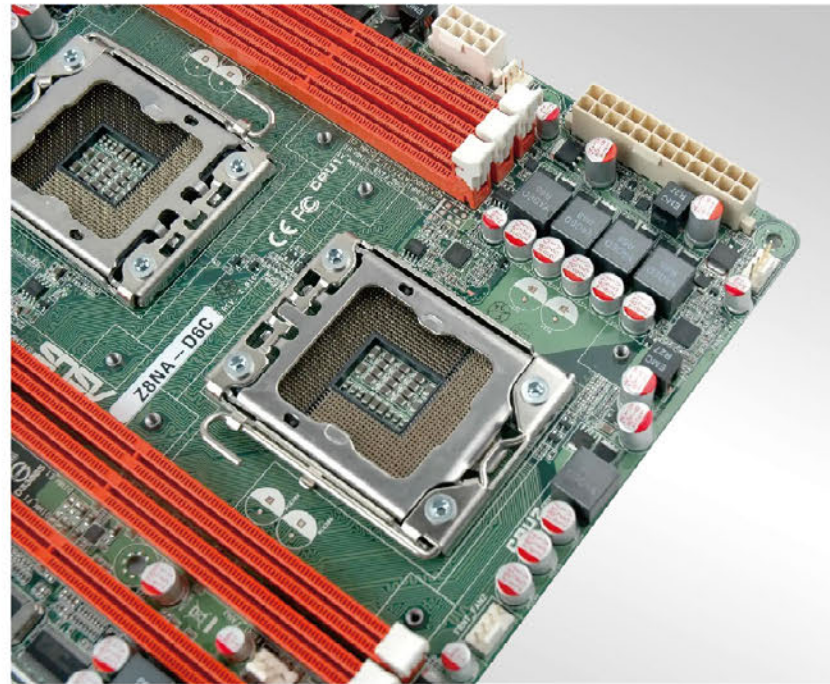
- Voltage: 250V max.
Current (at 30°C temperature rise):
Power: 30.0A max.
Signal: 1.0A max.
Contact Resistance (per contact):
Min Max
Power(milliohms)-0.11 0.02
Signal(milliohms) 0.35 0.47
Dielectric Withstanding Voltage: 1.500V
Insulation Resistance (Min.): 5.000 Megohms
Current interruption:
Power - 30.0A and 48V DC Signal - 1.0A at 30V

Physical

- Housing: LCP
Contact:
Power Contacts -Copper(Cu) alloy Signal Contacts-Copper (Cu) Alloy
Plating:
Contact Area-Select Gold/Solder Tail Area - Tin/Underplating-Nickel
Flammability Rating: UL 94V-0
Operating Temperature: -40 to +105°C



Card Edge Product Family: DDR DIMM/DDR SO DIMM



MECHANICAL PERFORMANCE

- 1.Insertion force (module to connector): 106.8N max
- 2.Terminal retention force: 300gf min.
- 3.Durability: 25cycles.

ELECTRICAL PERFORMANCE

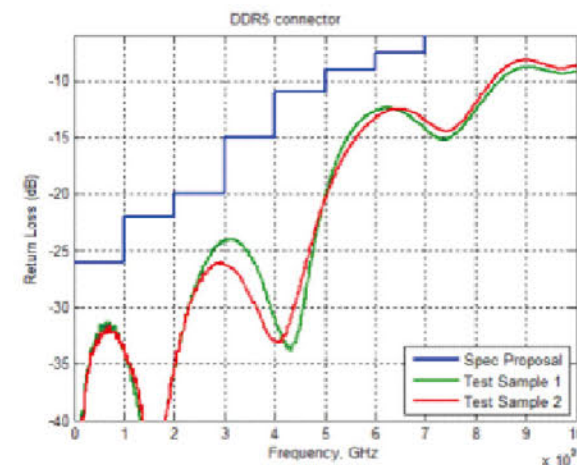
- 1.Low level contact resistance: 10mΩ initial, Δ10mΩ
- 2.Insulation resistance: 1MΩ min.
- 3.Dielectric withstanding voltage: 250VAC.
- 4.Current rating: 0.75A/pin De-rate

ENVIRONMENTAL

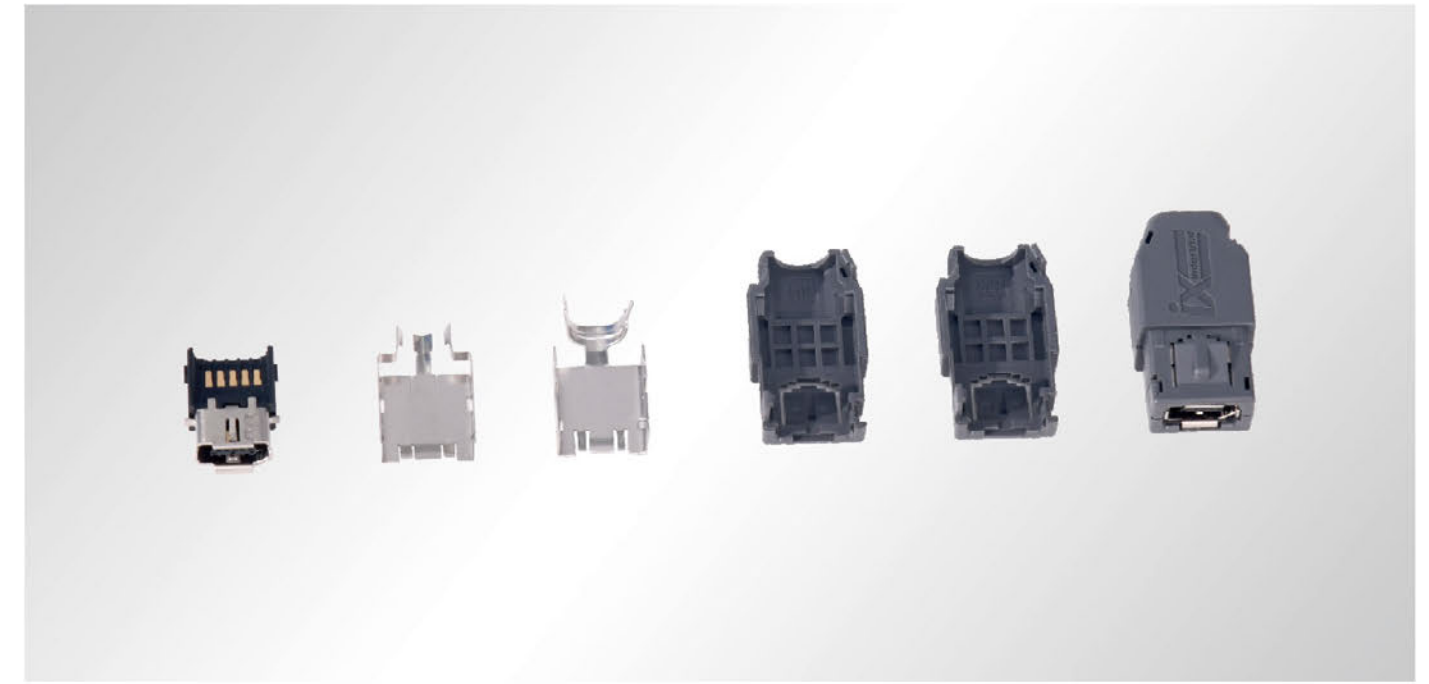
- 1.Flammability: UL 94 V-0
- 2.Low halogen: 1000ppm max. Cl, 1000ppm max Br.
- 3.Compliant with RoHS directive 2011/65/EU
- 4.Operating Temperature: -55°C to +85°C

SPECIFICATION

- 1.JEDEC SPEC:
DDR4 288pin: SO-016 (DIP), SO-018(SMT)
/ MO-309 (Module)
DDR5 288pin: SO-023 / MO-369
- 2.DELEC PRODUCT SPEC:
DDR4: DE-PS-0046
DDR5: DE-PS-0115



IX Series Connector (Industrial Transmission connector)



MATERIAL

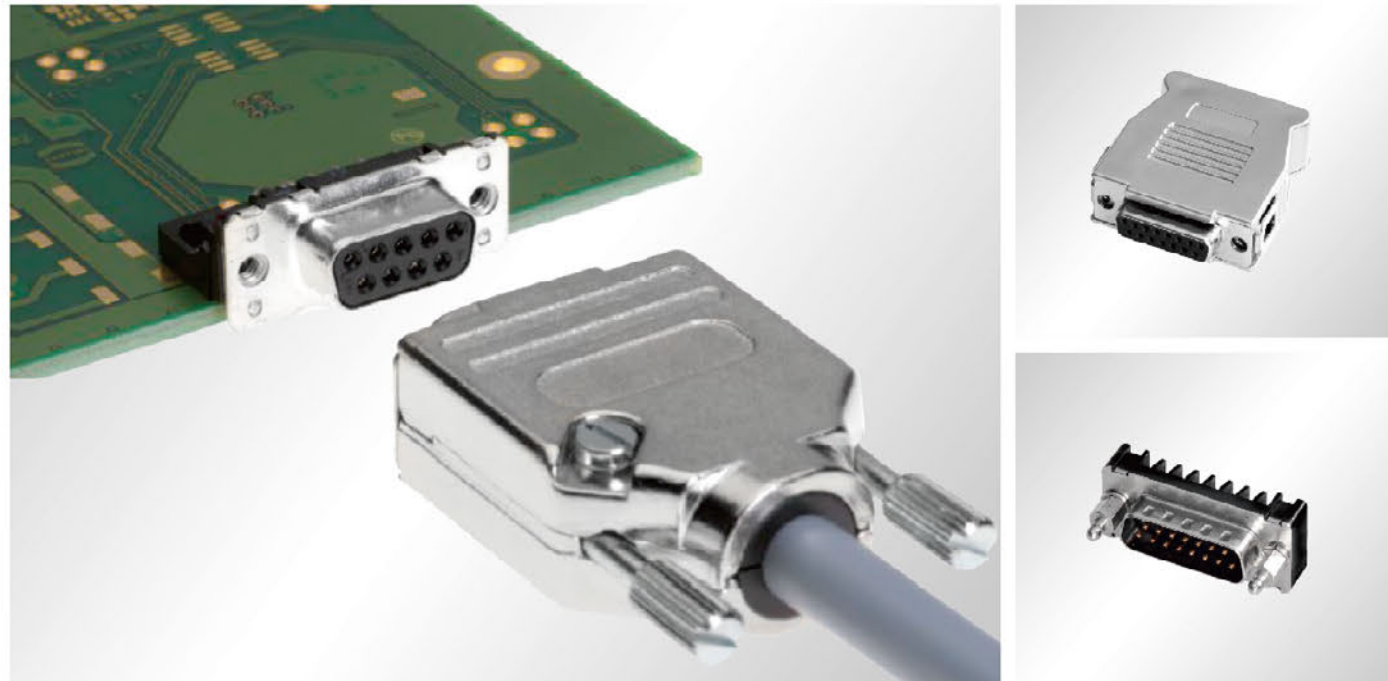
1. RoHS COMPLIANT PER EU DIRECTIVE 2011/65/EU AND AMENDMENTS.
2. STAINLESS STEEL, MATTE TIN OVER NICKEL PLATED.
3. INSERTS: HIGH TEMPERATURE RESISTANT ENGINEERING THERMOPLASTIC, GLASS REINFORCED, UL94V-0.
4. CONTACTS: COPPER ALLOY PLATED WITH GOLD OR PALLADIUM-NICKEL (SEE ORDERING CODE)
OVER 1.27μm (50μ") MINIMUM NICKEL ON THE MATING AREA AND MATTE TIN OVER NICKEL ON THE SMT TAILS. CODE 4 MATING AREA PLATING 1.27μm (50μ") GOLD
OPTION CONFORMS TO ASTM B488, TYPE 2, CODE C, CLASS 1.25.
MID-PLATE: STAINLESS-STEEL

Specifications

1. CONNECTORS ARE PROVIDED IN TAPE & REEL PACKAGING FOR PICK & PLACE PROCESSING
AND ARE SUITABLE FOR IR REFLOW SOLDERING OF PIN IN PASTE SHIELD TAILS AND SURFACE MOUNT CONTACT TAILS.
2. DESIGNED TO CONFORM TO REQUIREMENTS OF IEC 61076 PART 3-124 SPECIFICATION. THE A KEY FEATURE SHOWN IS INTENDED FOR USE WITH ETHERNET APPLICATIONS, EITHER 10/100 MBIT/S OR 1 TO 10 GBIT/S (CAT 5e, 6 & 6A).
3. CURRENT RATING:
1.5 A PER POSITION (30° MAX TEMPERATURE RISE PER UL1977 & CSA C22.2 NO 182.3 STANDARDS) VOLTAGE RATING: 50V AC rms OR 60V DC
4. OPERATING TEMPERATURE -55° TO +105°C.
5. DIELECTRIC WITHSTANDING VOLTAGE: 500V DC.
6. CONTACT RESISTANCE: 30 MILLIOHMS MAXIMUM.
7. INSULATION RESISTANCE: 500 MEGOHMS MINIMUM.
8. MATING & UNMATING FORCE: 25N (5.6 lbf) MAXIMUM.



D-SUB Series Connector



D-SUB Series

MATERIALS

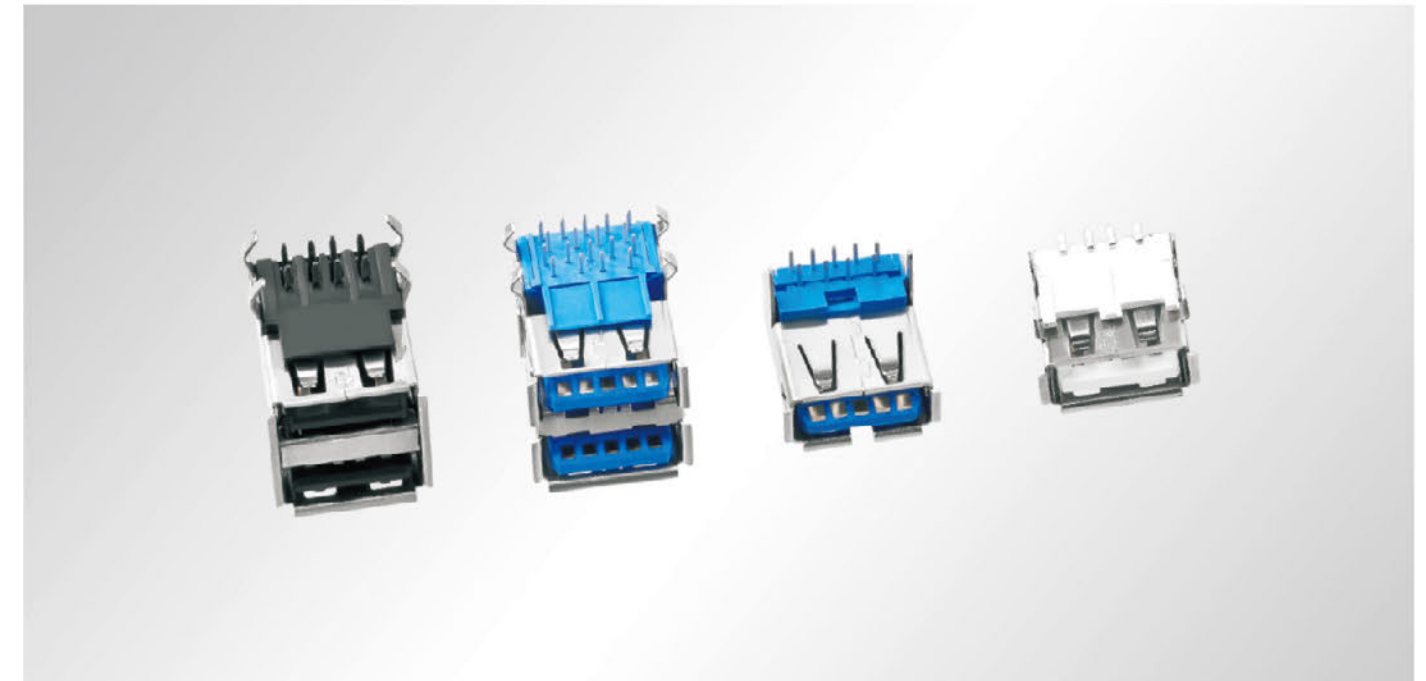
Insulator: high temperature thermoplastic, UL94V-0 Blue
 Contact terminal: 30 u" Au plated on contact area
 50u"min Matte Tin plated on solder area;
 50u"min Nickel underplating over all.
 Crust: SPCC, plated Ni

Specifications

1. Electrical requirements:
 Current rating: 1A
 Contact resistance: $\leq 30\text{m}\Omega$
 Insulation resistance: $\geq 1000\text{M}\Omega$
 Withstanding voltage: 500 V.r.m.s. 1mA.60s
2. Mechanical requirements
 Insertion force: $\leq 3.3\text{ N/pin}$
 Extraction force: $\geq 0.3\text{ N/pin}$
 Mechanical life: 200 cycles
3. Environment specification
 Working temperature: $-40^\circ\text{C} \sim +100^\circ\text{C}$
 Humidity: $\leq 93\%$ at 40°C
4. Applicable standard: IEC60807
5. Storing:
 Storing condition: temperature of $-10^\circ\text{C} \sim +40^\circ\text{C}$
 below 80% relative humidity
6. To prevent the pollution of the environment product
 info: In line with the European union RoHS



USB & HDMI Series Connector



HDMI Series

Material

1. Housing: LCP+30%G.F,UL94V-0,Black
2. Contact: Copper Alloy, Au And Sn Plated.
3. Shell: SK7, Ni Plated.

Specifications

Mating Force: 44.1N(4.5Kg) max.
 Unmating Force: 9.8N~39.2(1~4Kg).
 Durability: 10,000 Cycles.

ELECTRICAL CHARACTERISTIC

Current Rating: 0.5A Max.
 Voltage Rating: 40V AC Max.
 Contact Resistance: 30m Ohm Max.
 Insulation Resistance:
 100M Ohm Min(unmated)
 10M Ohm Min(mated)
 Dielectric Withstanding Voltage:
 500V AC Min

TEMPERATURE

Operating Temperature:
 $-40^\circ\text{C} \sim +85^\circ\text{C}$
 Storage Temperature:
 $-60^\circ\text{C} \sim +105^\circ\text{C}$

USB Series

Material

1. Housing: Nylon,PBT(UL94-VO)Color:White,Black, Blue or other colors are available
2. Contacts: Flat Pin: phosphor bronze plated with
 5u"/3u"/7u"/15u"/30u"Min hard gold plated over nickel.
3. Shielding: brass or spcc with nickel plated.

Specifications

Voltage Current Rating: USB(1A,30VAC),
 HDMI(0.5A. 40VDC)
 Insulation Resistance: 1000MQ Min.
 Contact Resistance: 30mQ Ma
 Dielectric Withstanding Voltage: 500V AC

USB2.0: Single USB2.0/Dual USB2.0(PTH solder type)
 available

Sing gle USB2.0(SMT solder type)available

USB3.0: Single USB3.0/Dual USB3.0(PTH solder type)
 available

Single USB3.0(SMT solder type)available"



Type C Connector

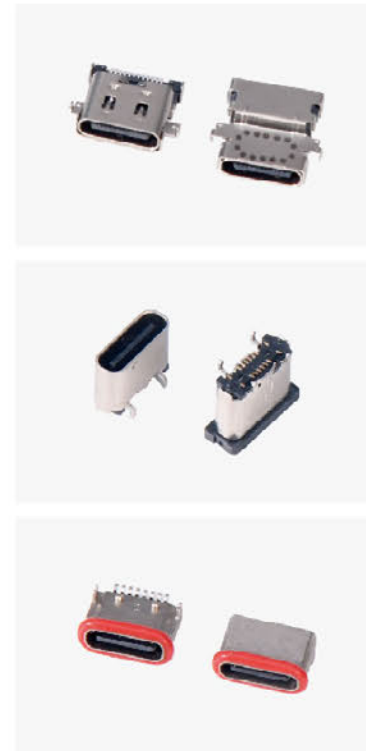


MATERIALS

1. HOUSING : LCP (UL 94V-0), BLACK.
2. TERMINAL : COPPER ALLOY, C18400 T=0.12
GOLD $Fu73u7$ PLATED ON
CONTACT AREA.
GOLD FLASH PLATING ON SOLDER TAIL.
NICKEL $50u''$ UNDERPLATED OVER ALL.
3. MID PLATE : STAINLESS STEEL, SUS301 T=0.15
4. SHELL : STAINLESS STEEL, SUS 301 T=0.30 NICKEL
 $50u''$ MIN PLATING
5. EMI : STAINLESS STEEL, SUS 304 T=0.10 NICKEL
 $50u''$ MIN PLATING

Specifications

1. CURRENT RATING :
5.0A FOR Vbus PIN,
1.25A FOR Vconn PIN,
0.25A FOR OTHER PINS.
2. CONTACT RESISTANCE : 40m Ω .
3. INSULATION RESISTANCE : 100M Ω MIN.
4. DIELECTRIC WITHSTANDING VOLTAGE : 100 VAC MIN.
5. OPERATING TEMPERATURE : -40°C TO +85°C.
6. MATING FORCE : 5~20N.
7. UNMATING FORCE : 8~20N.
8. DURABILITY : 10,000 CYCLES.
9. RECOMMENDED PROCESS :
THE PEAK TEMPERATURE ON THE BOARD SHALL
MAINTAIN 260°C.
10. SALT SPRAY : 48 hour



RJ45 1XN Series Integrated Connector Modules



RJ45 1XN Series

1XN PORT Tab Up/Tab Down 10/100/1000/2.5G/5G/10G
Base-T RJ45 Connector



Material

1. Housing: Nylon, PBT (UL94-V0)
Color: Black or other colors available
2. Contacts:
Flat Pin: 0.35mm thickness phosphor bronze plated with
 $3u''/6u''/15u''/30u''/50u''$ Min hard gold plated.
3. Shielding: 0.20mm thickness brass with nickel plated.

Specification Characteristic

1. Port: 1X1/1X2/1X4
2. Position Number: 8 Positions or 10 Positions available
3. Contact Number: 8 Contacts
4. Tab Up or Tab Down available.
5. Shielding: Non-Shielded/Shielded with EMI Finger/Shielded
without EMI Finger
6. Magnetics: 10/100 Base-T, 10/100/1000 Base-T Schematic
available.
7. LED: Without LED/ With LED option (Different colors of LED
option available)
8. 1X1 port Tab up / SMT Type available.

Feature

Shielded RJ45 connector with integrated 10/100 or Gigabit
Ethernet
Complies with IEEE802.3 standards
Jack cavity conforms to FCC rules and regulation Part 68
subpart F.
Integrated design conserves valuable board space.
Minimum interwinding breakdown voltage of 1500Vrms.
Adaptable, modular design provides higher reliability.
Operating temperature: 0°C to +70°C
Storage temperature: 40°C to +85°C

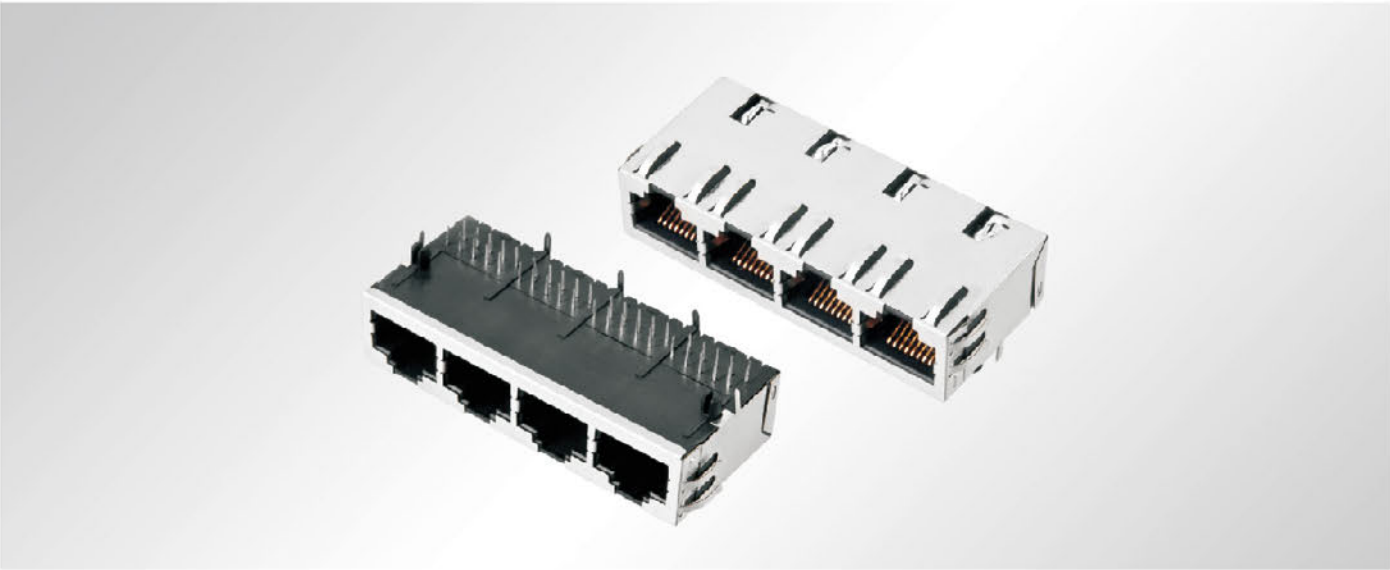
ELECTRICAL CHARACTERISTICS @ 25°C 10/100 BASE-T Product

Turn Ratio: 1:1±3%.
Primary Inductance:
350uH MIN. @100KHz, 100mVRMS, 8mA DC BIAS.
Hi-Pot(Isolation Voltage):
Input to Output isolation 1500Vrms/2250VDC.
Insertion Loss:
1MHz-100MHz -1.1dB MAX.
Return Loss:(Load:100 ohms)
1MHz-30MHz -18dB MIN.
30MHz-60MHz -18+20Log(F/30)dB MIN
60MHz-80MHz -12dB MIN.
CM to CM Rejection:
1MHz-100MHz -30dB MIN.
CM to DM Rejection:
1MHz-100MHz -35dB MIN.
Cross Talk:
1MHz-100MHz -30dB MIN.

10/100/1000 BASE-T Product

Turn Ratio: 1:1±3%.
Primary Inductance:
350uH MIN. @100KHz, 100mVRMS, 8mA DC BIAS.
Hi-Pot(Isolation Voltage):
Input to Output isolation 1500Vrms/2250VDC Min.
Insertion Loss:
100KHz-1MHz -1.1dB MAX.
1MHz-65MHz -0.8dB MAX.
65MHz-100MHz -1.0dB MAX.
100MHz-125MHz -1.2dB MAX.
Return Loss:(Load:100 ohms)
1MHz-40MHz -18dB MIN.
40MHz-100MHz -12+20Log(F/80)dB MIN
CM to CM Rejection:
1MHz-100MHz -30dB MIN.
CM to DM Rejection:
1MHz-100MHz -35dB MIN.
Cross Talk:
1MHz-40MHz -30dB MIN.
40MHz-100MHz -33+20Log(F/50)dB MIN

RJ45 1XN Series Integrated Connector Modules



RJ45 1XN Series

1XN PORT Tab Up /Tab Down 10/100/1000/2.5G/5G/10G
Base-T RJ45 Connector



- Material**
- 1.Housing:Nylon,PBT(UL94-V0)
Color:Black or other colors available
 - 2.Contacts:
Flat Pin:0.35mm thickness phosphor bronze plated with 3u"/6u"/15u"/30u"/50u" Min hard gold plated.
 - 3.Shielding:0.20mm thickness brass with nickel plated.
- Specification Characteristic**
- 1.Port: 1X1/1X2/1X4
 - 2.Position Number:8 Positions or 10 Positions available
 - 3.Contact Number: 8 Contacts
 - 4.Tab Up available.
 - 5.Shielding: Non-Shielded/Shielded with EMI Finger/Shielded without EMI Finger
 - 6.Magnetics:10/100 Base-T, 10/100/1000 Base-T Schematic available.
 - 7.LED:Without LED/ With LED option (Differnet colors of LED option available)

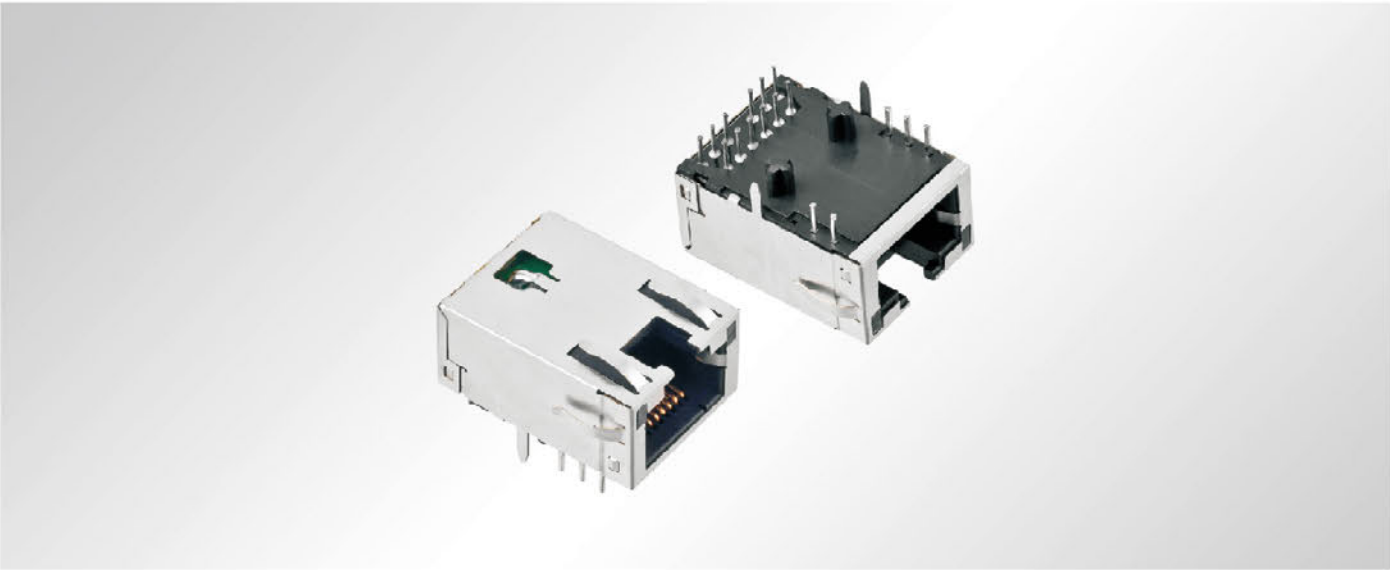
Feature

Shielded RJ45 connector with integrated 10/100 or Gigabit Ethernet
Complies with IEEE802.3 standards
Jack cavity conforms to FCC rules and regulation Part 68 subpart F.
Integrated design conserves valuable board space.
Minimum interwinding breakdown voltage of 1500Vrms.
Adaptable,modular design provides higher reliability.
Operating temperature:0°C to +70°C
Storage temperature:-40°C to +85°C

- ELECTRICAL CHARACTERISTICS @ 25°C**
- 10/100 BASE-T Product**
- Turn Ratio: 1:1±3%.
- Primary Inductance:
350uH MIN.@100KHz,100mVRMS,8mA DC BIAS.
Hi-Pot(Isolation Voltage):
Input to Output isolation 1500Vrms/2250VDC.
- Insertion Loss:
1MHz-100MHz -1.1dB MAX.
Return Loss:(Load:100 ohms)
1MHz-30MHz -18dB MIN.
30MHz-60MHz -18+20Log(F/30)dB MIN
60MHz-80MHz -12dB MIN.
- CM to CM Rejection:
1MHz-100MHz -30dB MIN.
- CM to DM Rejection:
1MHz-100MHz -35dB MIN.
- Cross Talk:
1MHz-100MHz -30dB MIN.

- 10/100/1000 BASE-T Product**
- Turn Ratio: 1:1±3%.
- Primary Inductance:
350uH MIN.@100KHz,100mVRMS,8mA DC BIAS.
Hi-Pot(Isolation Voltage):
Input to Output isolation 1500Vrms/2250VDC.
- Insertion Loss:
100KHz-1MHz -1.1dB MAX.
1MHz-65MHz -0.8dB MAX.
65MHz-100MHz -1.0dB MAX.
100MHz-125MHz -1.2dB MAX.
- Return Loss:(Load:100 ohms)
1MHz-40MHz -18dB MIN.
40MHz-100MHz -12+20Log(F/80)dB MIN
- CM to CM Rejection:
1MHz-100MHz -30dB MIN.
- CM to DM Rejection:
1MHz-100MHz -35dB MIN.
- Cross Talk:
1MHz-40MHz -30dB MIN.
40MHz-100MHz -33+20Log(F/50)dB MIN

RJ45 1X1 Series Integrated Connector Modules



RJ45 1X1 Series

1XN PORT Tab Up/Tab Down 10/100/1000/2.5G/10G
Base-T RJ45 Connector



- Material**
- 1.Housing:Nylon,PBT(UL94-V0)
Color:Black or other colors available
 - 2.Contacts:
Flat Pin:0.35mm thickness phosphor bronze plated with 3u"/6u"/15u"/30u"/50u" Min hard gold plated.
 - 3.Shielding:0.20mm thickness brass with nickel plated.
- Specification Characteristic**
- 1.Port: 1X1
 - 2.Position Number:8 Positions or 12 Positions available
 - 3.Contact Number: 8 Contacts
 - 4.Tab Up or Tab Down available.
 - 5.Shielding: Shielded with EMI Finger/Shielded without EMI Finger
 - 6.Magnetics:10/100 Base-T, 10/100/1000 Base-T,10G Base-T Schematic available.
 - 7.LED:Without LED/ With LED option (Differnet colors of LED option available)

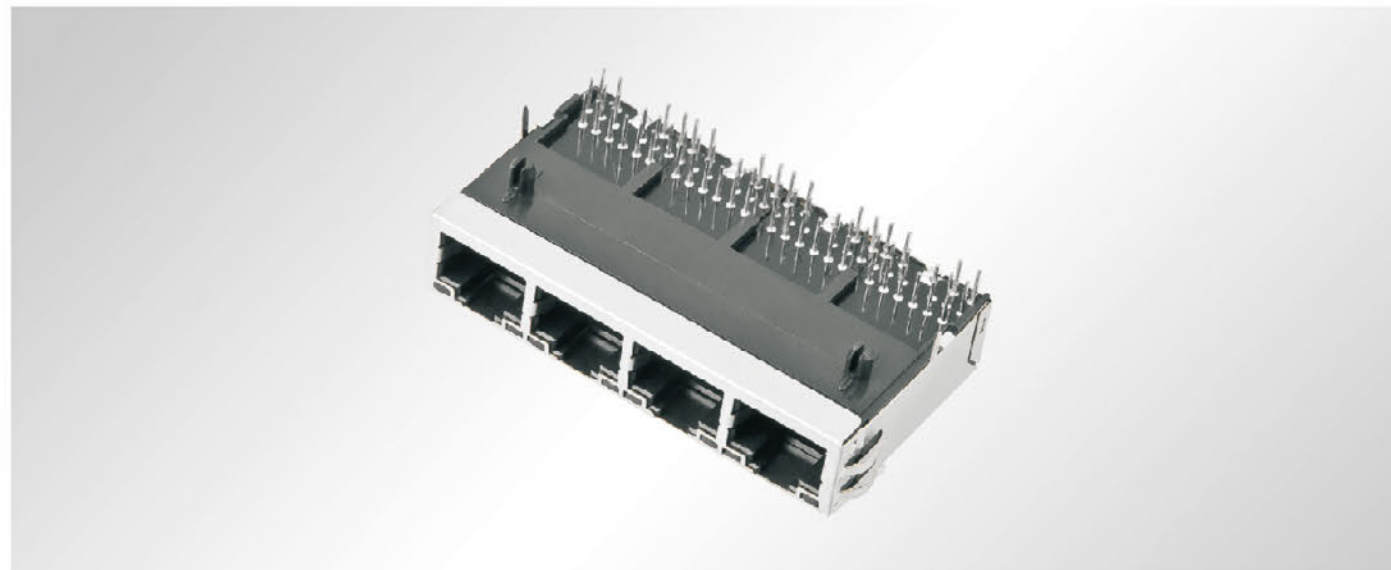
Feature

Ultra low profile design
Shielded RJ45 connector with integrated 10/100BASE-T or 10/100/100BASE-T or 10GBASE-T Ethernet
Complies with IEEE802.3/IEEE802.3an standards
Jack cavity conforms to FCC rules and regulation Part 68 subpart F.
Integrated design conserves valuable board space.
Minimum interwinding breakdown voltage of 1500Vrms.
Adaptable,modular design provides higher reliability.
Operating temperature:0°C to +70°C
Storage temperature:-40°Cto +85°C

- ELECTRICAL CHARACTERISTICS @ 25°C**
- 10/100/1000 BASE-T Product**
- Turn Ratio: 1:1±3%.
- Primary Inductance:
350uH MIN.@100KHz,100mVRMS,8mA DC BIAS.
Hi-Pot(Isolation Voltage):
Input to Output isolation 1500Vrms/2250VDC.
- Insertion Loss:
1MHz-100MHz -1.1dB MAX.
Return Loss:(Load:100 ohms)
1MHz-30MHz -18dB MIN.
30MHz-60MHz -18+20Log(F/30)dB MIN
60MHz-80MHz -12dB MIN.
- CM to CM Rejection:
1MHz-100MHz -30dB MIN.
- CM to DM Rejection:
1MHz-100MHz -35dB MIN.
- Cross Talk:
1MHz-100MHz -30dB MIN.

- 10G BASE-T Product**
- Turn Ratio: 1:1±3%.
- Primary Inductance:
120uH MIN.@100KHz,100mVRMS,8mA DC BIAS.
Hi-Pot(Isolation Voltage):
Input to Output isolation 1500Vrms/2250VDC.
- Insertion Loss:
1MHz-20MHz -0.8dB MAX.
50MHz -1.0dB MAX.
200MHz -1.2dB MAX.
400MHz -2.0dB MAX.
500MHz -3.0dB MAX.
- Return Loss:(Load:100 ohms)
1MHz-40MHz -22dB MIN.
40MHz-100MHz -20dB MIN.
100MHz-200MHz -18dB MIN.
200MHz-300MHz -15dB MIN.
300MHz-400MHz -10dB MIN.
400MHz-500MHz -8dB MIN.
- CM to CM Rejection:
1MHz-500MHz -20dB MIN.
- CM to DM Rejection:
1MHz-250MHz -30dB MIN.
250MHz-500MHz -22dB MIN.
- Cross Talk:
1MHz-100MHz -30dB MIN.
100MHz-500MHz -20dB MIN

RJ45 1XN Series Integrated Connector Modules



RJ45 1XN Series

1XN PORT Tab Up/Tab Down 10/100/1000/2.5G/5G/10G

Base-T RJ45 Connector

With POE/POE+/UPOE/POE++ Options



Material

1. Housing: Nylon, PBT (UL94-V0)
Color: Black or other colors available
2. Contacts:
Flat Pin: 0.35mm thickness phosphor bronze plated with 3u"/6u"/15u"/30u"/50u" Min hard gold plated.
3. Shielding: 0.20mm thickness brass with nickel plated.

Specification Characteristic

1. Port: 1X1/1X2/1X4
2. Position Number: 8 Positions or 10 Positions available
3. Contact Number: 8 Contacts
4. Tab Up or Tab Down available.
5. Shielding: Non-Shielded/Shielded with EMI Finger/Shielded without EMI Finger
6. Magnetics: 10/100 Base-T, 10/100/1000 Base-T Schematic available.
7. LED: Without LED/ With LED option (Different colors of LED option available)

Feature

Shielded RJ45 connector with integrated 10/100 or Gigabit Ethernet
Complies with IEEE802.3 standards
Jack cavity conforms to FCC rules and regulation Part 68 subpart F.
Integrated design conserves valuable board space.
Minimum interwinding breakdown voltage of 1500Vrms.
Adaptable, modular design provides higher reliability.
Operating temperature: 0°C to +70°C
Storage temperature: -40°C to +85°C

ELECTRICAL CHARACTERISTICS @ 25°C

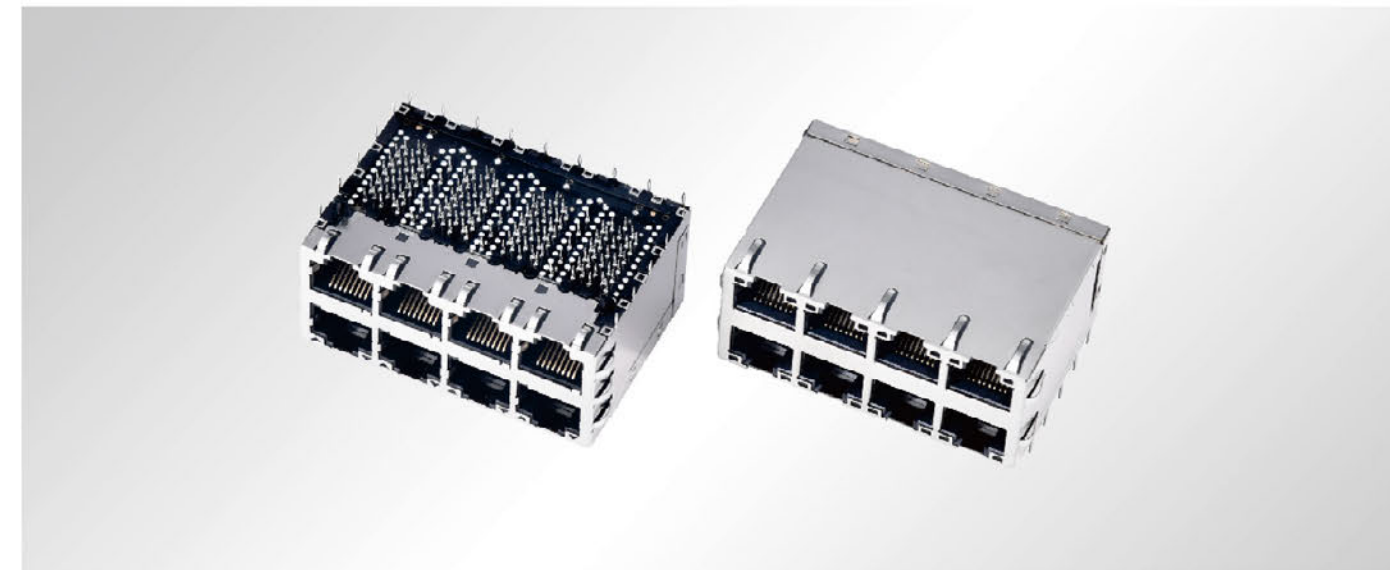
10/100 BASE-T Product

Turn Ratio: 1:1±3%.
Primary Inductance:
350uH MIN. @100KHz, 100mVRMS, 8mA DC BIAS.
Hi-Pot (Isolation Voltage):
Input to Output isolation 1500Vrms/2250VDC.
Insertion Loss:
1MHz-100MHz -1.1dB MAX.
Return Loss (Load: 100 ohms)
1MHz-30MHz -18dB MIN.
30MHz-60MHz -18+20Log(F/30)dB MIN
60MHz-80MHz -12dB MIN.
CM to CM Rejection:
1MHz-100MHz -30dB MIN.
CM to DM Rejection:
1MHz-100MHz -35dB MIN.
Cross Talk:
1MHz-100MHz -30dB MIN.

10/100/1000 BASE-T Product

Turn Ratio: 1:1±3%.
Primary Inductance:
350uH MIN. @100KHz, 100mVRMS, 8mA DC BIAS.
Hi-Pot (Isolation Voltage):
Input to Output isolation 1500Vrms/2250VDC.
Insertion Loss:
100KHz-1MHz -1.1dB MAX.
1MHz-65MHz -0.8dB MAX.
65MHz-100MHz -1.0dB MAX.
100MHz-125MHz -1.2dB MAX.
Return Loss (Load: 100 ohms)
1MHz-40MHz -18dB MIN.
40MHz-100MHz -12+20Log(F/80)dB MIN
CM to CM Rejection:
1MHz-100MHz -30dB MIN.
CM to DM Rejection:
1MHz-100MHz -35dB MIN.
Cross Talk:
1MHz-40MHz -30dB MIN.
40MHz-100MHz -33+20Log(F/50)dB MIN

RJ45 2XN Series Integrated Connector Modules

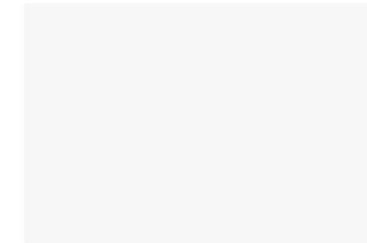
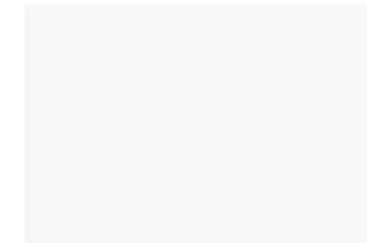
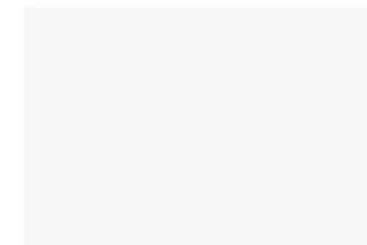


RJ45 2XN Series

Stacked Ports 10/100/1000/2.5G/5G/10G

Base-T RJ45 Modules

With POE/POE+/UPOE/POE++ Options



Material

1. Housing: Nylon, PBT (UL94-V0)
Color: Black
2. Contacts: Flat Pin: 0.35mm thickness phosphor bronze plated with 3u"/6u"/15u"/30u"/50u" Min hard gold plated.
3. Shielding: 0.20mm thickness brass with nickel plated.

Specification Characteristic

1. Port: 2X1, 2X2, 2X4, 2X6, 2X8
2. Position Number: 10 or 12 Positions available
3. Contact Number: 8 Contacts
4. Shielding: Shielded with EMI Finger/Shielded without EMI Finger
6. Magnetics: 10/100 Base-T, 10/100/1000 Base-T, POE, POE Plus Schematic available.
7. ESD/Surge Protection option.
8. LED: Without LED/ With Back LED option (Different colors of LED option available)

Feature

Shielded RJ45 connector with integrated 10/100 or Gigabit Ethernet
Complies with IEEE802.3af/at standards
Jack cavity conforms to FCC rules and regulation Part 68 subpart F.
Integrated design conserves valuable board space.
Minimum interwinding breakdown voltage of 1500Vrms.
Adaptable, modular design provides higher reliability.
Operating temperature: 0°C to +70°C
Storage temperature: -40°C to +85°C

ELECTRICAL CHARACTERISTICS @ 25°C

10/100 BASE-T Product

Turn Ratio: 1:1±3%.
Primary Inductance:
350uH MIN. @100KHz, 100mVRMS, 8mA DC BIAS.
Hi-Pot (Isolation Voltage):
Input to Output isolation 1500Vrms/2250VDC.
Insertion Loss:
1MHz-100MHz -1.1dB MAX.
Return Loss (Load: 100 ohms)
1MHz-30MHz -18dB MIN.
30MHz-60MHz -18+20Log(F/30)dB MIN
60MHz-80MHz -12dB MIN.
CM to CM Rejection:
1MHz-100MHz -30dB MIN.
CM to DM Rejection:
1MHz-100MHz -35dB MIN.
Cross Talk:
1MHz-100MHz -30dB MIN.

10/100/1000 BASE-T Product

Turn Ratio: 1:1±3%.
Primary Inductance:
350uH MIN. @100KHz, 100mVRMS, 8mA DC BIAS.
Hi-Pot (Isolation Voltage):
Input to Output isolation 1500Vrms/2250VDC.
Insertion Loss:
100KHz-1MHz -1.1dB MAX.
1MHz-65MHz -0.8dB MAX.
65MHz-100MHz -1.0dB MAX.
100MHz-125MHz -1.2dB MAX.
Return Loss (Load: 100 ohms)
1MHz-40MHz -18dB MIN.
40MHz-100MHz -12+20Log(F/80)dB MIN
CM to CM Rejection:
1MHz-100MHz -30dB MIN.
CM to DM Rejection:
1MHz-100MHz -35dB MIN.
Cross Talk:
1MHz-40MHz -30dB MIN.
40MHz-100MHz -33+20Log(F/50)dB MIN
Balanced DC Line current/Voltage rating (PSE Pins)
720mA Maximum @ 57V Continuous

RJ45 2XN Series Integrated Connector Modules



RJ45 2XN Series

Stacked Ports 10/100/1000/2.5G/5G/10G
Base-t RJ45 Modules
With POE/POE+/UPOE/POE++ Options



Material

- 1.Housing:Nylon,PBT(UL94-V0)
Color:Black
- 2.Contacts:
Flat Pin:0.35mm thickness phosphor bronze plated
with 3u"/6u"/15u"/30u"/50u" Min hard gold plated.
- 3.Shielding:0.20mm thickness brass with nickel plated.

Specification Characteristic

- 1.Port:2X4,2X6,2X8
- 2.Position Number:12 Positions available
- 3.Contact Number: 8 Contacts
- 4.Shielding:Shielded with EMI Finger/Shielded
without EMI Finger
- 6.Magnetics:10/100 Base-T,POE, POE Plus Schematic
available.
- 7.LED:Without LED/ With Front LED option (Diffenet
colors of LED option available)

Feature

Shielded RJ45 connector with integrated 10/100
POE/POE Plus Ethernet
Complies with IEEE802.3af/at standards
Jack cavity conforms to FCC rules and regulation
Part 68 subpart F.
Integrated design conserves valuable board space.
Minimum interwinding breakdown voltage of
1500Vrms.
Adaptable,modular design provides higher
reliability.
Operating temperature:0°C to +70°C
Storage temperature:-40°C to +85°C

ELECTRICAL CHARACTERISTICS @ 25°C

10/100 BASE-T Product

Turn Ratio: 1:1±3%.
Primary Inductance:
350uH MIN.@100KHz,100mVRMS,8mA DC BIAS.
Hi-Pot(Isolation Voltage):
Input to Output isolation 1500Vrms/2250VDC.
Insertion Loss:
1MHz-100MHz -1.1dB MAX.
Return Loss:(Load:100 ohms)
1MHz-30MHz -18dB MIN.
30MHz-60MHz -18+20Log(F/30)dB MIN
60MHz-80MHz -12dB MIN.
CM to CM Rejection:
1MHz-100MHz -30dB MIN.
CM to DM Rejection:
1MHz-100MHz -35dB MIN.
Cross Talk:
1MHz-100MHz -30dB MIN.

10/100/1000 BASE-T Product

Turn Ratio: 1:1±3%.
Primary Inductance:
350uH MIN.@100KHz,100mVRMS,8mA DC BIAS.
Hi-Pot(Isolation Voltage):
Input to Output isolation 1500Vrms/2250VDC.
Insertion Loss:
100KHz-1MHz -1.1dB MAX.
1MHz-65MHz -0.8dB MAX.
65MHz-100MHz -1.0dB MAX.
100MHz-125MHz -1.2dB MAX.
Return Loss:(Load:100 ohms)
1MHz-40MHz -18dB MIN.
40MHz-100MHz -12+20Log(F/80)dB MIN
CM to CM Rejection:
1MHz-100MHz -30dB MIN.
CM to DM Rejection:
1MHz-100MHz -35dB MIN.
Cross Talk:
1MHz-40MHz -30dB MIN.
40MHz-100MHz -33+20Log(F/50)dB MIN

RJ45 integrated connector with USB2.0/3.0 combo modules



RJ45+USB & RJ45 Vertical Serie

RJ45+USB2.0/3.0 & 10/10/1000/2.5G
Base-T Connector



Material

- 1.Housing:Nylon,PBT(UL94-V0)
- 2.Contacts:
Flat Pin:0.35mm thickness phosphor bronze plated
with 3u"/6u"/15u"/30u"/50u" Min hard gold plated.
- 3.Shielding:0.20mm thickness brass with nickel plated.

Specification Characteristic

- 1.Port: 1X1
- 4.DE68 Vertical 180 Degree type design/ DE67 RJ45 with
USB Combination
- 5.Shielding:Shielded with EMI Finger/Shielded without
EMI Finger
- 6.Magnetics:10/100 Base-T, 10/100/1000 Base-T
Schematic available.
- 7.LED:Without LED/ With LED option (Diffenet colors of
LED option available)
- 8.RJ45 with single USB2.0/ RJ45 with single USB3.0. available
RJ45 with dual USB3.0/ RJ45 with dual USB3.0. available

Feature

Shielded RJ45 connector with integrated 10/100 or
Gigabit Ethernet
Complies with IEEE802.3 standards
Jack cavity conforms to FCC rules and regulation Part
68 subpart F.
Integrated design conserves valuable board space.
Minimum interwinding breakdown voltage of 1500Vrms.
Adaptable,modular design provides higher reliability.
Operating temper ature:0°C to +70°C
Storage temperature:-40°C to +85°C

ELECTRICAL CHARACTERISTICS @ 25°C

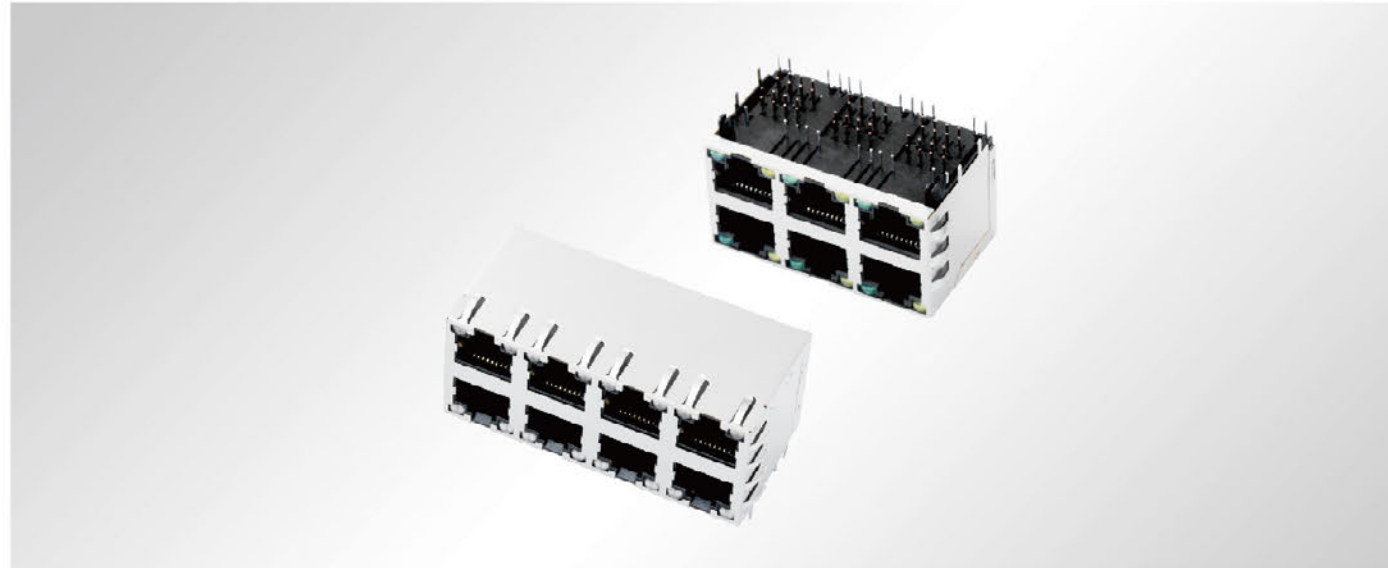
10/100 BASE-T Product

Turn Ratio: 1:1±3%.
Primary Inductance:
350uH MIN.@100KHz,100mVRMS,8mA DC BIAS.
Hi-Pot(Isolation Voltage):
Input to Output isolation 1500Vrms/2250VDC.
Insertion Loss:
1MHz-100MHz -1.1dB MAX.
Return Loss:(Load:100 ohms)
1MHz-30MHz -18dB MIN.
30MHz-60MHz -18+20Log(F/30)dB MIN
60MHz-80MHz -12dB MIN.
CM to CM Rejection:
1MHz-100MHz -30dB MIN.
CM to DM Rejection:
1MHz-100MHz -35dB MIN.
Cross Talk:
1MHz-100MHz -30dB MIN.

10/100/1000 BASE-T Product

Turn Ratio: 1:1±3%.
Primary Inductance:
350uH MIN.@100KHz,100mVRMS,8mA DC BIAS.
Hi-Pot(Isolation Voltage):
Input to Output isolation 1500Vrms/2250VDC.
Insertion Loss:
100KHz-1MHz -1.1dB MAX.
1MHz-65MHz -0.8dB MAX.
65MHz-100MHz -1.0dB MAX.
100MHz-125MHz -1.2dB MAX.
Return Loss:(Load:100 ohms)
1MHz-40MHz -18dB MIN.
40MHz-100MHz -12+20Log(F/80)dB MIN
CM to CM Rejection:
1MHz-100MHz -30dB MIN.
CM to DM Rejection:
1MHz-100MHz -35dB MIN.
Cross Talk:
1MHz-40MHz -30dB MIN.
40MHz-100MHz -33+20Log(F/50)dB MIN

RJ45 2XN Module Jack Without Magnetics Connector



RJ45 2XN Series

RJ 45 Module Jack Without Magnetics



Material

- 1.Housing:Nylon,PBT(UL94-V0)Color:Black, Gray or other colors available.
- 2.Contacts:
Round Pin:0.46mm diameter phosphor bronze hard temper with hard gold plating thickness options(Fu"/ 3u"/6u"/15u"/30u"/50u")over 50u" min nickel.
Flat Pin:0.35mm thickness phosphor bronze plated with 3u"/6u"/15u"/30u"/50u" Min hard gold plated over nickel.
- 3.Shielding:0.20mm thickness brass with nickel plated.

Specification Characteristic

- 1.Port: 2X1,2X2,2X4,2X6,2X8
- 2.Position Number:8 Positions available
- 3.Contact Number: 8 Contacts
- 4.Shielding:Shielded with EMI Finger/Shielded without EMI Finger
- 5.LED:Without LED/ With LED option (Differnet colors of LED option available)



Electrical

- 1.Current Rating:1.5Amps per contact
- 2.Voltage Rating: 125Volts AC
- 3.Contact Resistance:30 miliohms Max
- 4.Insulation resistance:500Megohms Min @ 500VDC.
- 5.Dielectric Withstanding Voltage:Contact to contact 1000VAC @ 60HZ

Feature

Shielded RJ45 Modular Jack (withou magnetics).
Jack cavity conforms to FCC rules and regulation Part 68 subpart F.
Operating temperature:-40°C to +85°C
Storage temperature:-40°C to +85°C

RJ45 1XN Module Jack Without Magnetics Connector



RJ45 1XN Series

RJ45 Module Jack Without Magnetics

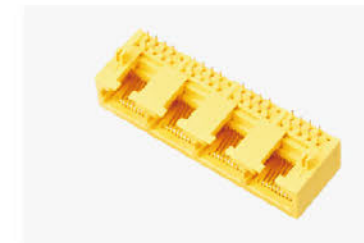


Material

- 1.Housing:Nylon,PBT(UL94-V0)
Color:Black,Gray or other colors available.
- 2.Contacts:
Round Pin:0.46mm diameter phosphor bronze hard temper with hard gold plating thickness options(Fu"/ 3u"/6u"/15u"/30u"/50u")over 50u" min nickel.
Flat Pin:0.35mm thickness phosphor bronze plated with 3u"/6u"/15u"/30u"/50u" Min hard gold plated over nickel.
- 3.Shielding:0.20mm thickness brass with nickel plated.

Specification Characteristic

- 1.Port: 1X1,1X2,1X4,1X8
- 2.Position Number:8 Positions available
- 3.Contact Number: 8 Contacts
- 4.Shielding:Without Shield/Shielded with EMI Finger/ Shielded without EMI Finger
- 5.LED:Without LED/ With LED option (Differnet colors of LED option available)



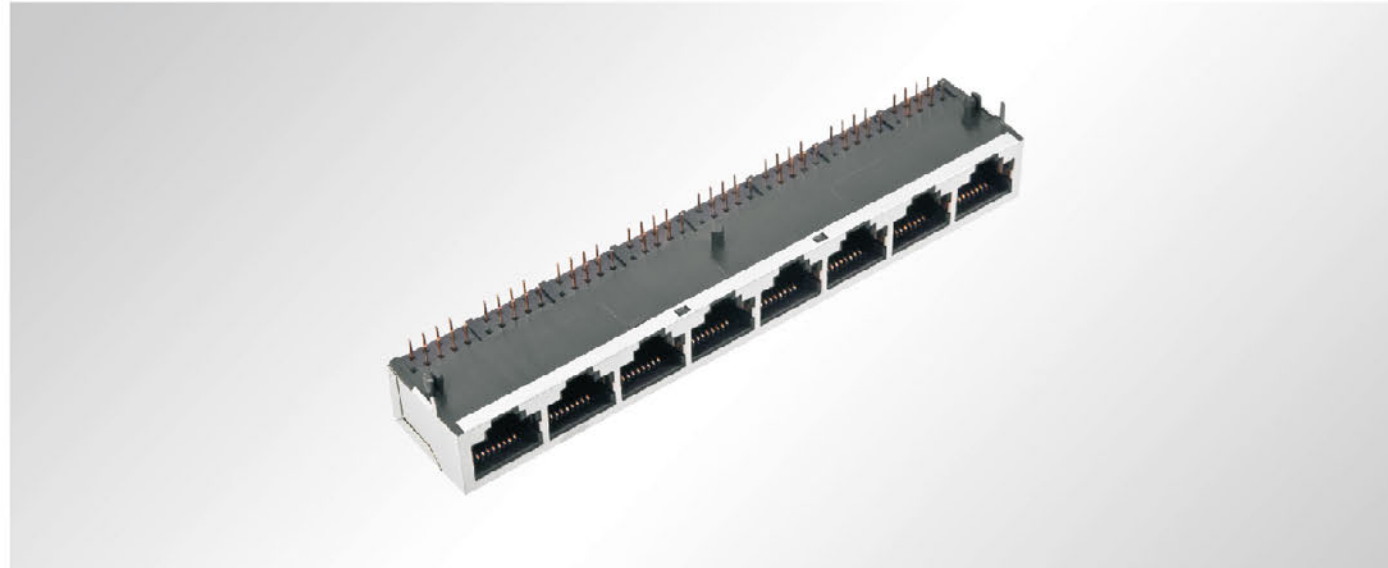
Electrical

- 1.Current Rating:1.5Amps per contact
- 2.Voltage Rating: 125Volts AC
- 3.Contact Resistance:30 miliohms Max
- 3.Insulation resistance:500Megohms Min @ 500VDC.
- 4.Dielectric Withstanding Voltage:Contact to contact 1000VAC @ 60HZ

Feature

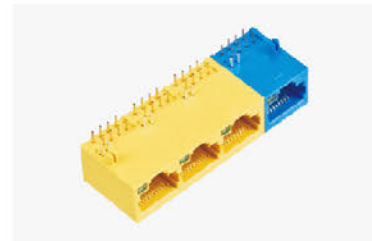
Shielded RJ45 Modular Jack (withou magnetics).
Jack cavity conforms to FCC rules and regulation Part 68 subpart F.
Operating temperature:-40°C to +85°C
Storage temperature:-40°C to +85°C

RJ45 1XN Module Jack Without Magnetics Connector



RJ45 1XN Series

RJ 45 Module Jack Without Magnetics



Material

- 1.Housing:Nylon,PBT(UL94-V0)
Color:Black,Gray or other colors available.
- 2.Contacts:
Round Pin:0.46mm diameter phosphor bronze hard temper with hard gold plating thickness options(Fu"/3u"/6u"/15u"/30u"/50u")over 50u" min nickel.
Flat Pin:0.35mm thickness phosphor bronze plated with 3u"/6u"/15u"/30u"/50u" Min hard gold plated over nickel.
- 3.Shielding:0.20mm thickness brass with nickel plated.

Specification Characteristic

- 1.Port: 1X1,1X2,1X5,1X6,1X8
- 2.Position Number:8 Positions/10 Positions available
- 3.Contact Number: 8 Contacts /10 Contacts
- 4.Shielding:without Shield/Shielded with EMI Finger/Shielded without EMI Finger
- 5.LED:Without LED/ With LED option (Different colors of LED option available)

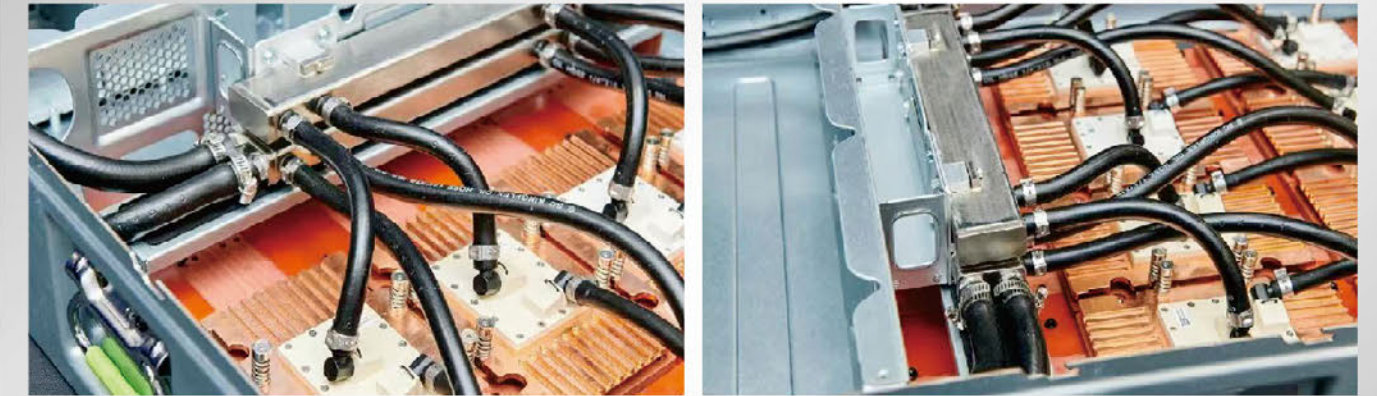
Electrical

- 1.Current Rating:1.5Amps per contact
- 2.Voltage Rating: 125Volts AC
- 3.Contact Resistance:30 milliohms Max
- 4.Insulation resistance:500Megohms Min @ 500VDC.
- 5.Dielectric Withstanding Voltage:Contact to contact 1000VAC @ 60HZ

Feature:

Shielded RJ45 Modular Jack (withou magnetics).
Jack cavity conforms to FCC rules and regulation Part 68 subpart F.
Operating temperature: -40°C to +85°C
Storage temperature:-40°C to +85°C

Radiator



Material:

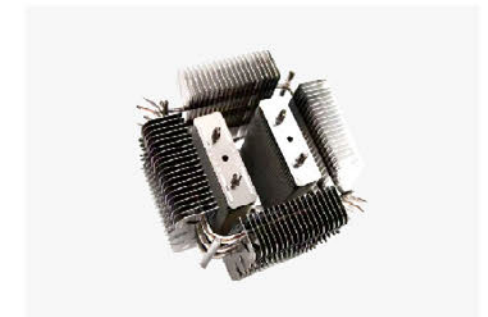
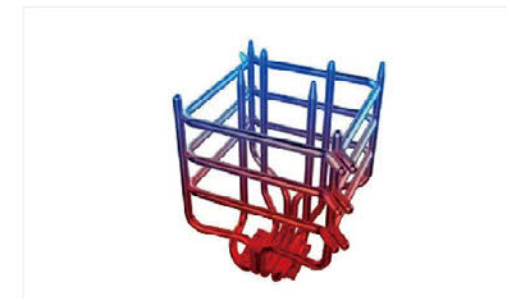
- 1.Sink:Copper heat pipe with aluminum fin
- 2.Pedestal:Copper
- 3.Plating : Ni plating
- 4.Contact Surface medium: Thermal paste or grease

Electrical:

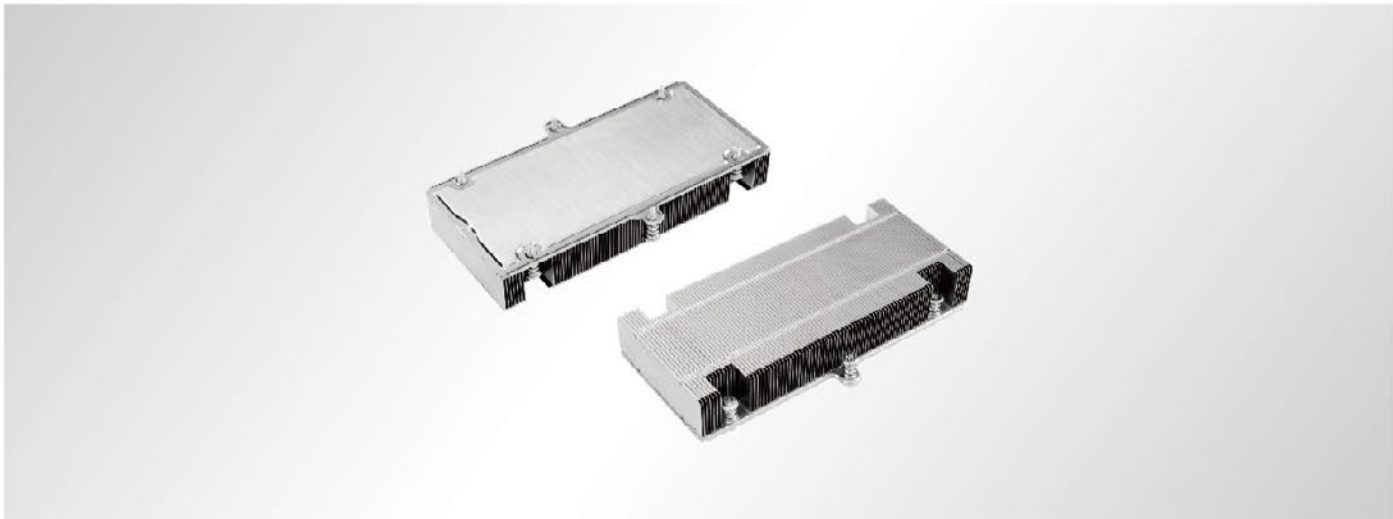
- 1.Voltage Rating: 12V
- 2.Current Rating:0.25 -2.5Amps option
3. Fan speed:800-1500RPM
4. Rated Power:3W-30W option

Feature

1. Anti-gravity pure copper heat pipe, fast conduction of chip heat
2. PWM intelligent speed regulation, high performance fan.
3. Innovative design and excellent quality
4. Multi-platform support
- 5.Operating Temperature:0°C to 85°C
- 6.Storage Temperature:-40°C to 105°C



Vapor Chamber and Heat Sink



Vapor Chamber and Heat Sink

Material
Color: Silver, Copper and other color available
Pedestal: Copper
Sink: Aluminum and Copper
Plating: Ni 50° Min
Contact Surface Medium: Thermal Paste or Grease

Feature
Operating Temperature: 0 °C to 80 °C
Storage Temperature: -40 °C to 130 °C
Pressure Resistance: 3.0kg/cm*2
Thermal Shock: -40°C to 100°C 500 time
Life Time: 10 years

Specifications
Qmax: 350 W
Min Heat Resistance: 0.152 K/W
Sink Height: 1U
Sink Thickness: 0.45mm
Pedestal Thickness: 3.1mm
Pedestal Area: 144 cm*2
Flatness: <50µm

